



CPEEC & CPSSC 2022

Nov 5-7, 2022

# **Power Supplies: Heterogeneous Integration - Benefits & Limitations**

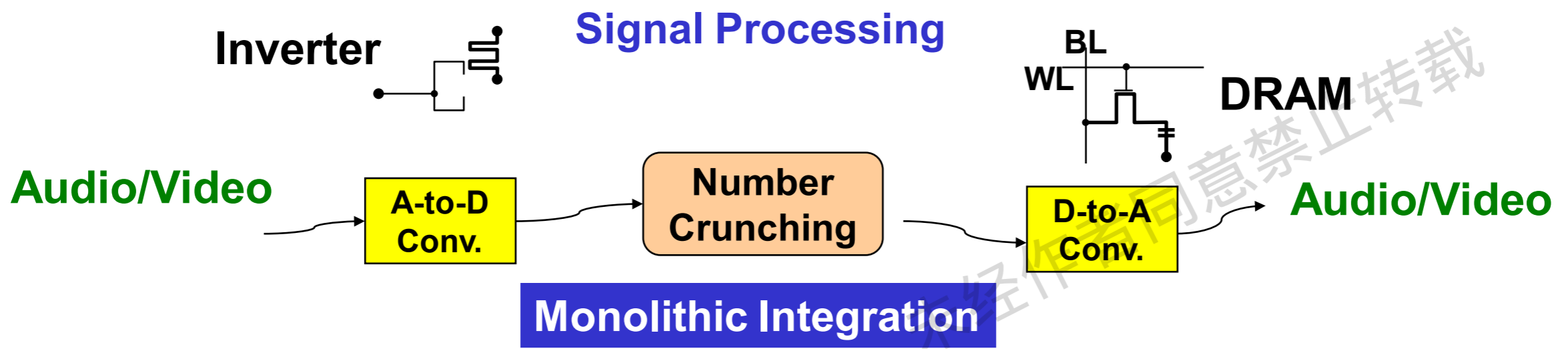
by

Fred C Lee

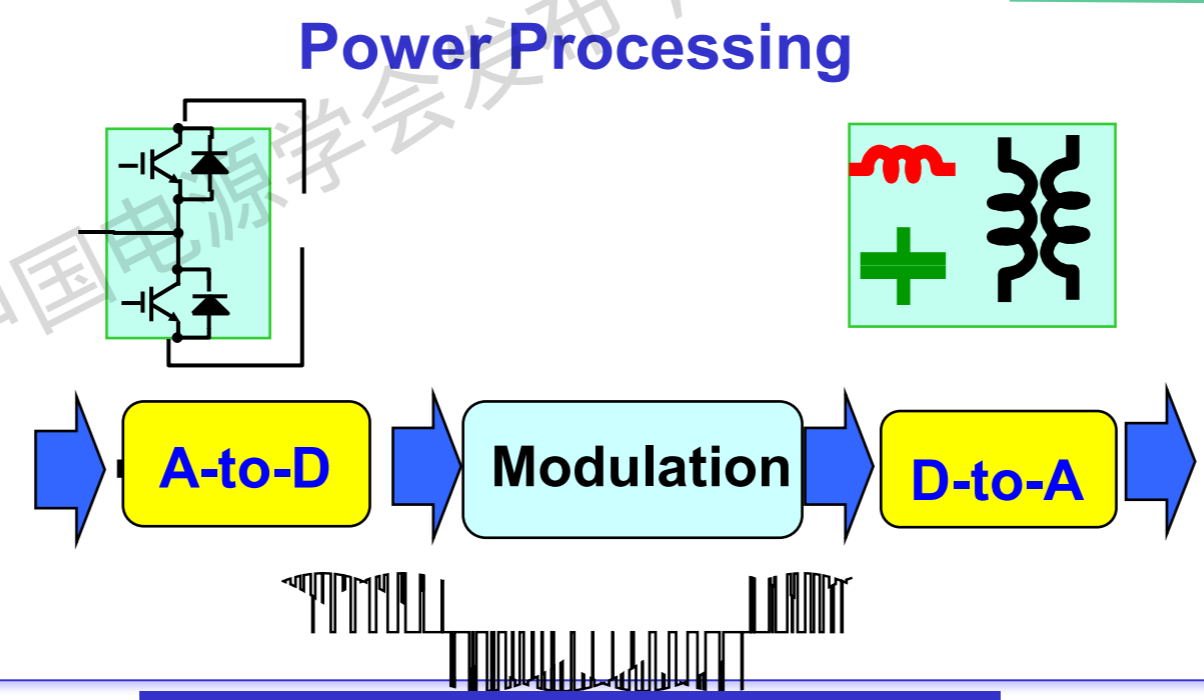
Center for Power Electronics Systems

Virginia Tech

# Micro-electronics vs Power Electronics



**PV**

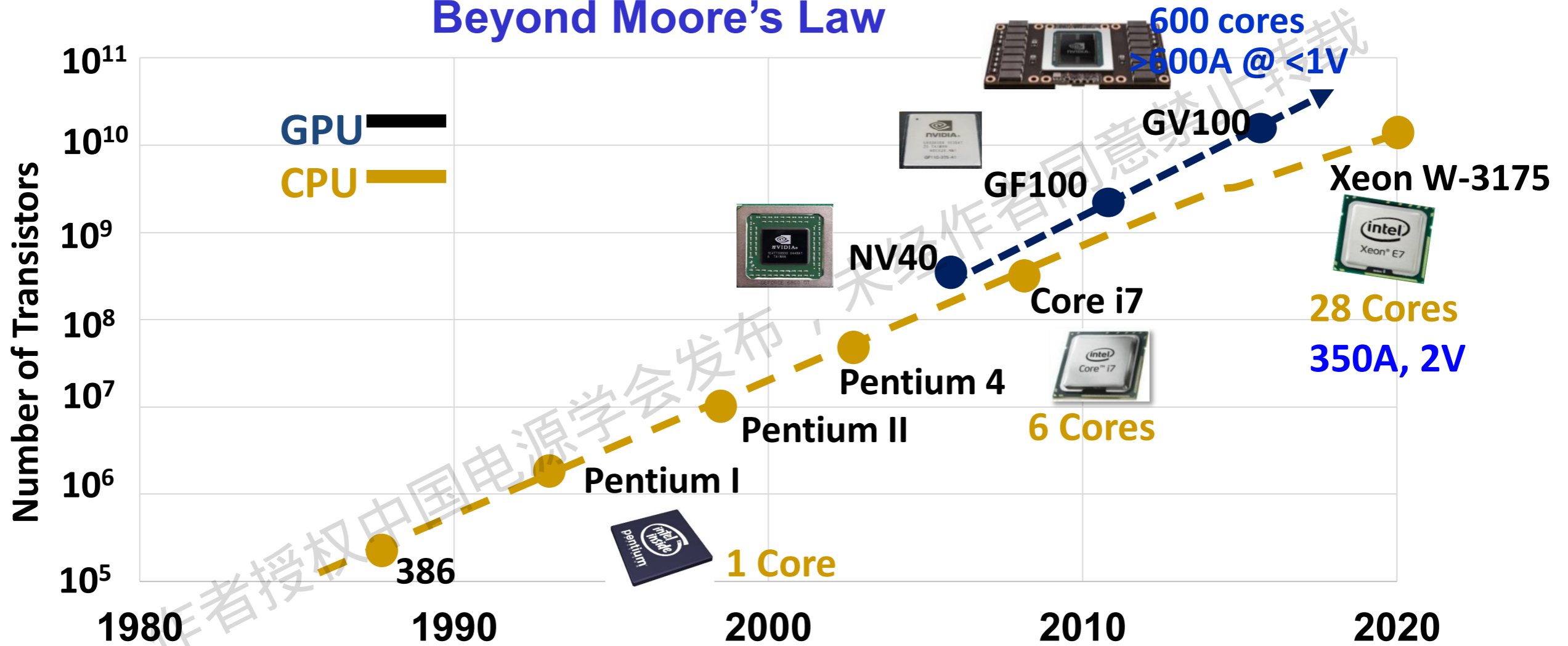


**60 Hz**

**Heterogeneous Integration**

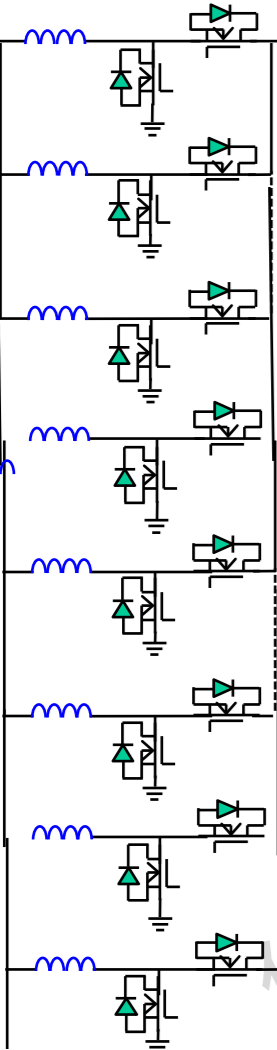
# Microprocessor Trends

## Beyond Moore's Law

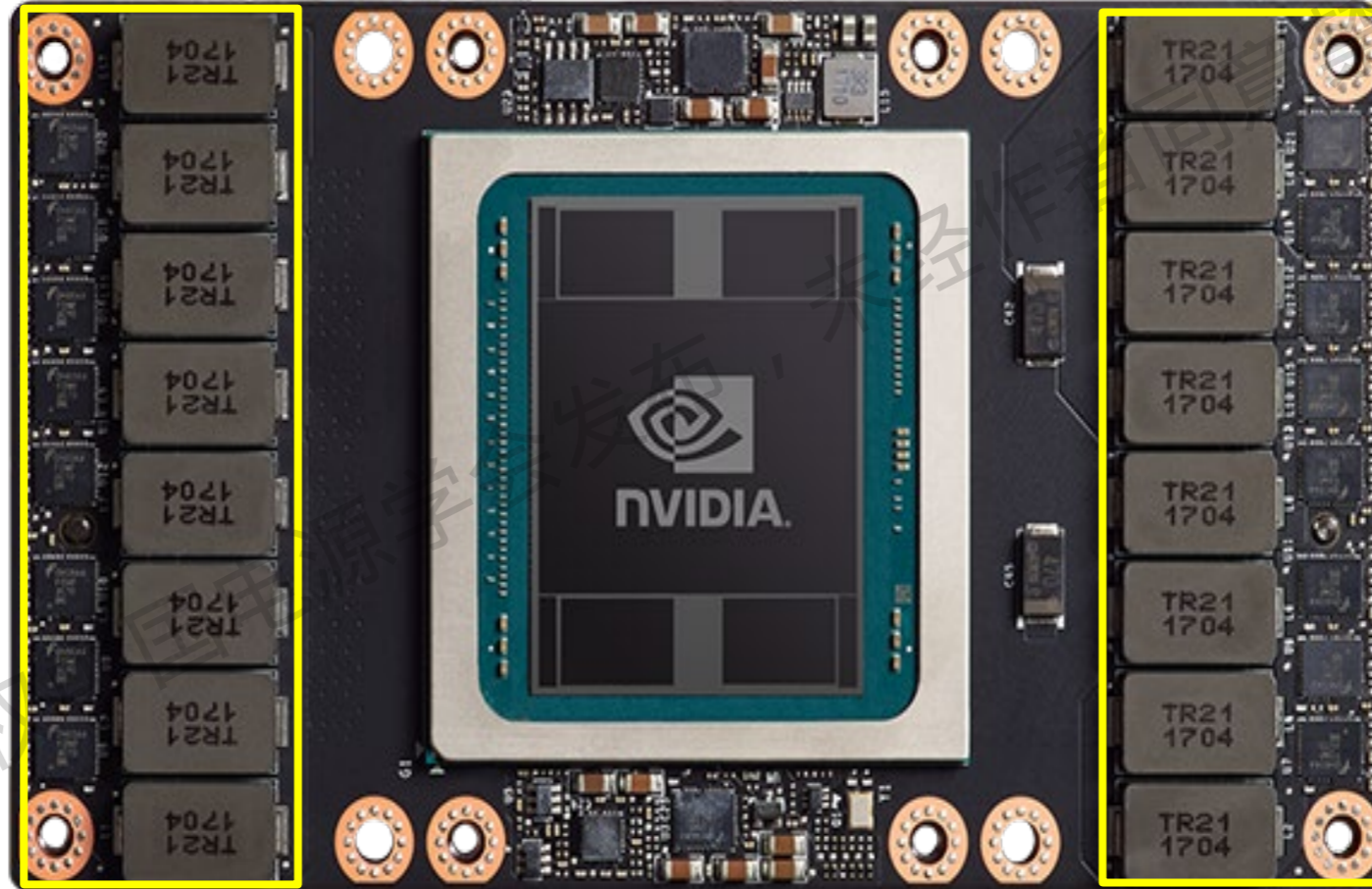


# CPU/GPU with “Embedded Power”

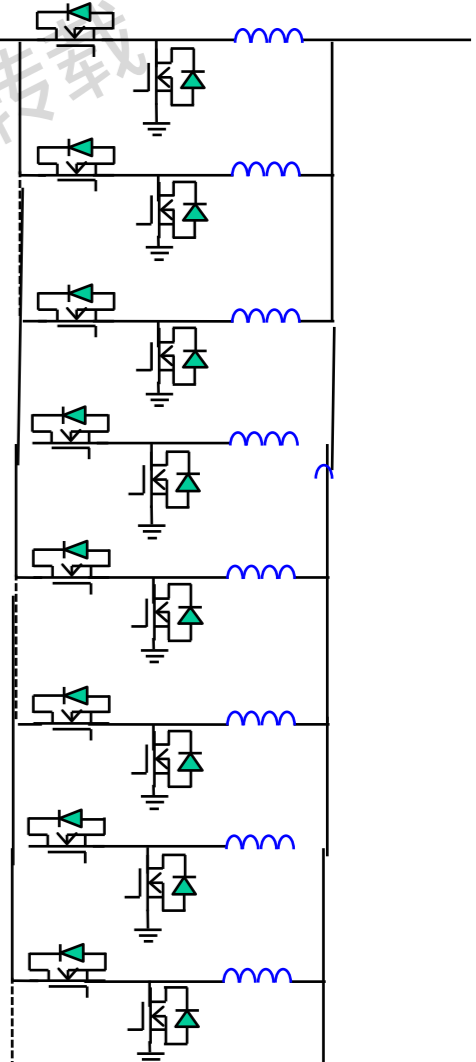
12V/1V



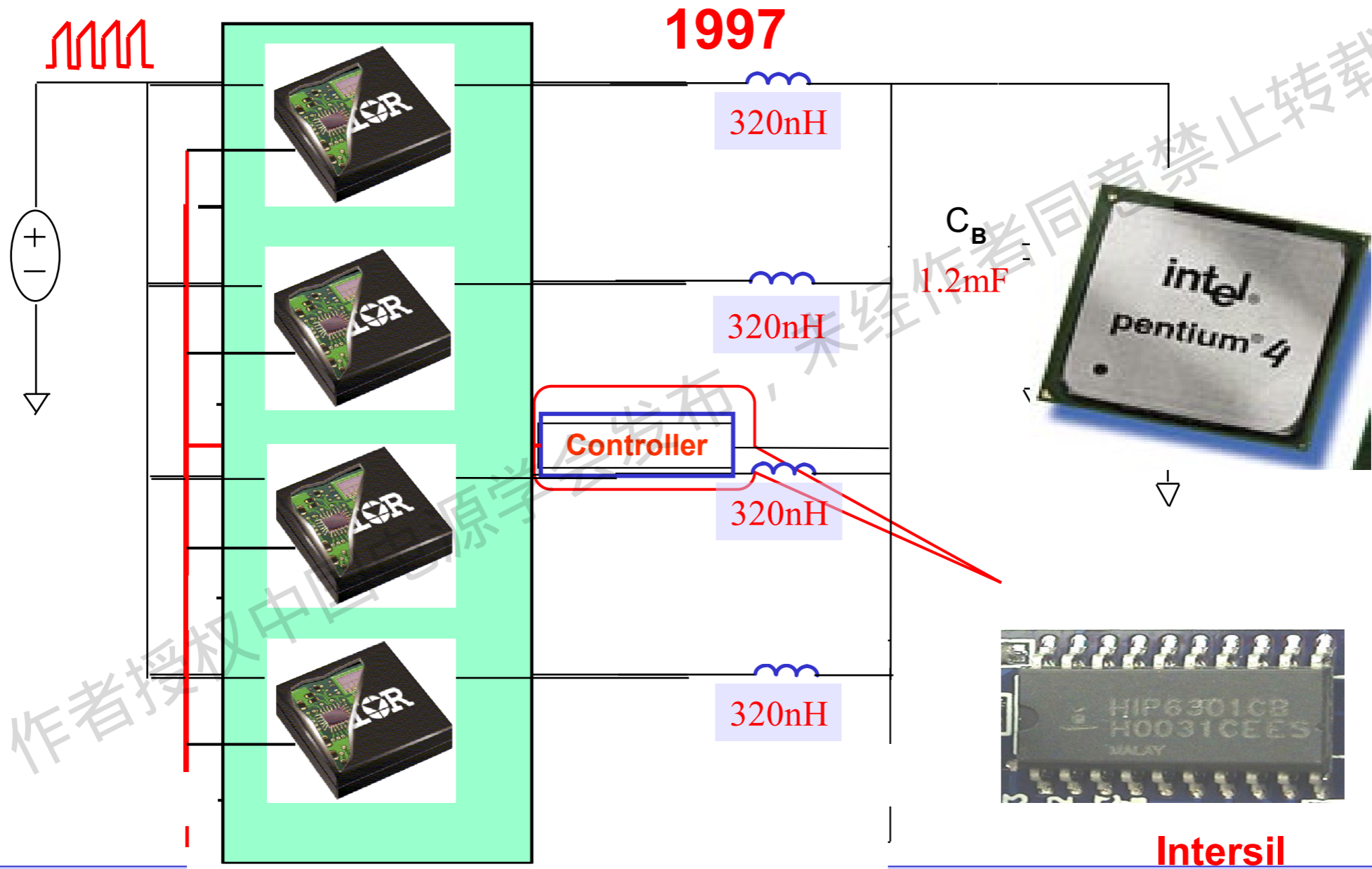
GV100: 16 phase > 600A. Slew rate >1000A/us



12V/1V

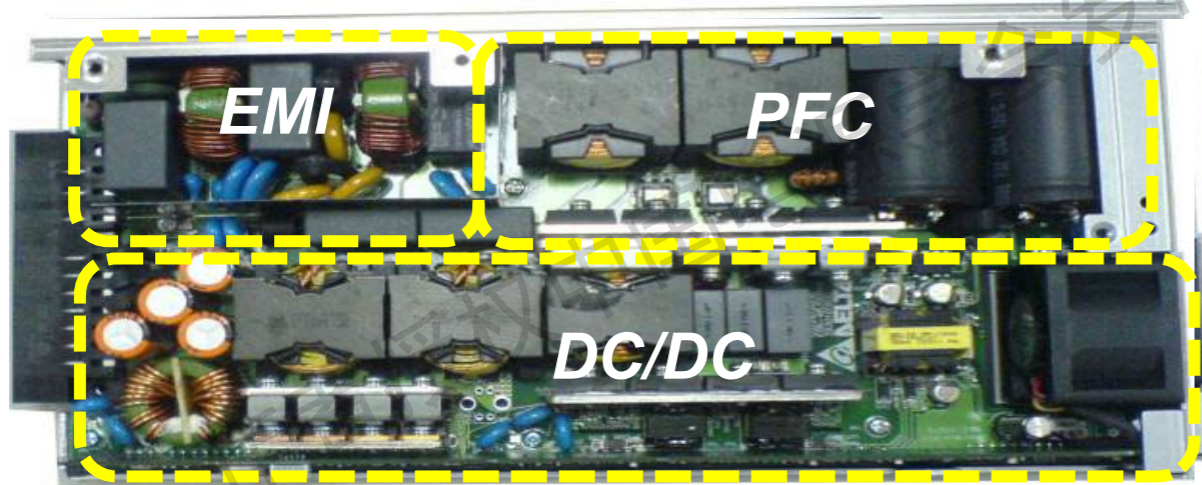
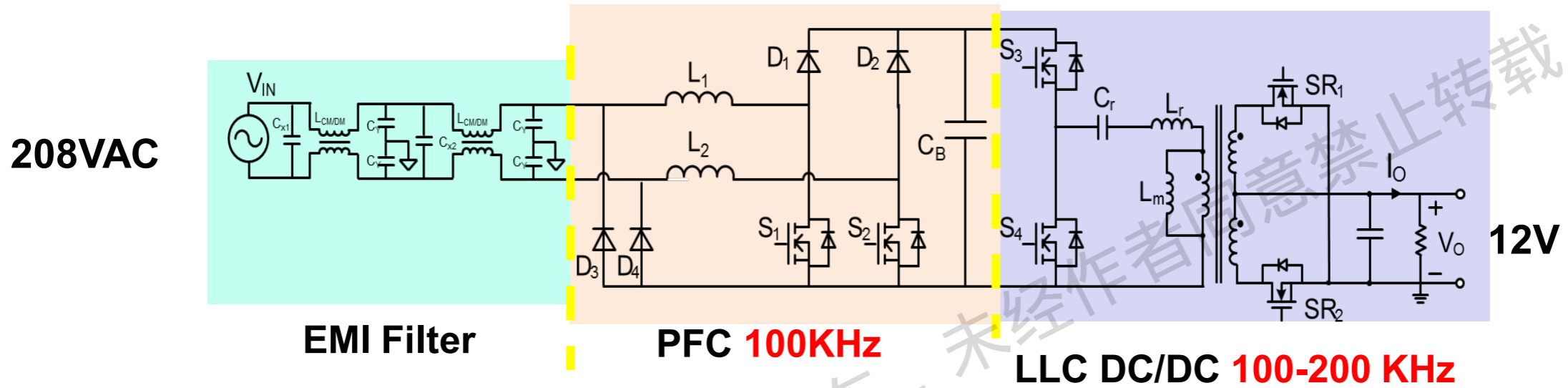


# “Integration” of Voltage Regulation Modules

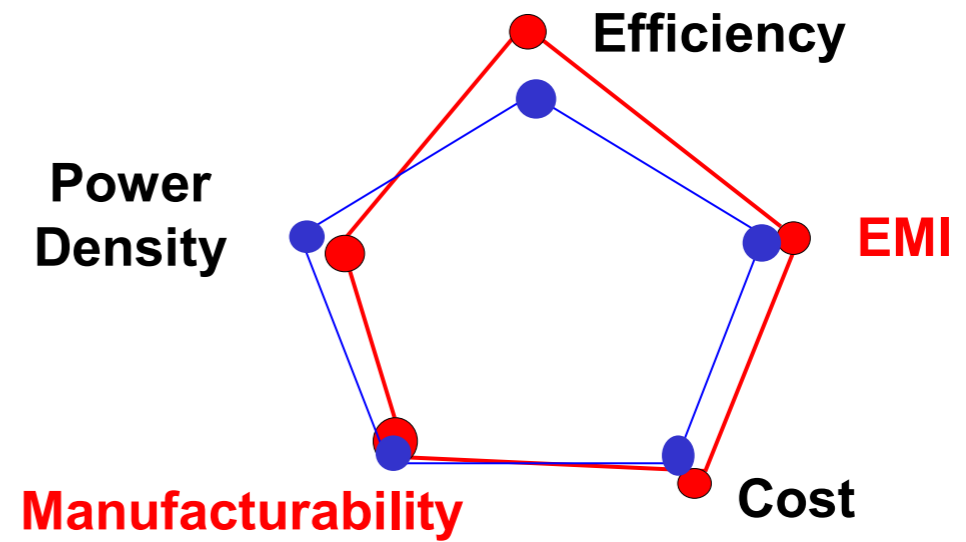


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# “External Power” : Server Power Supply for Data Center



**Matured Product** 96-97% and 30-40 W/in<sup>3</sup>

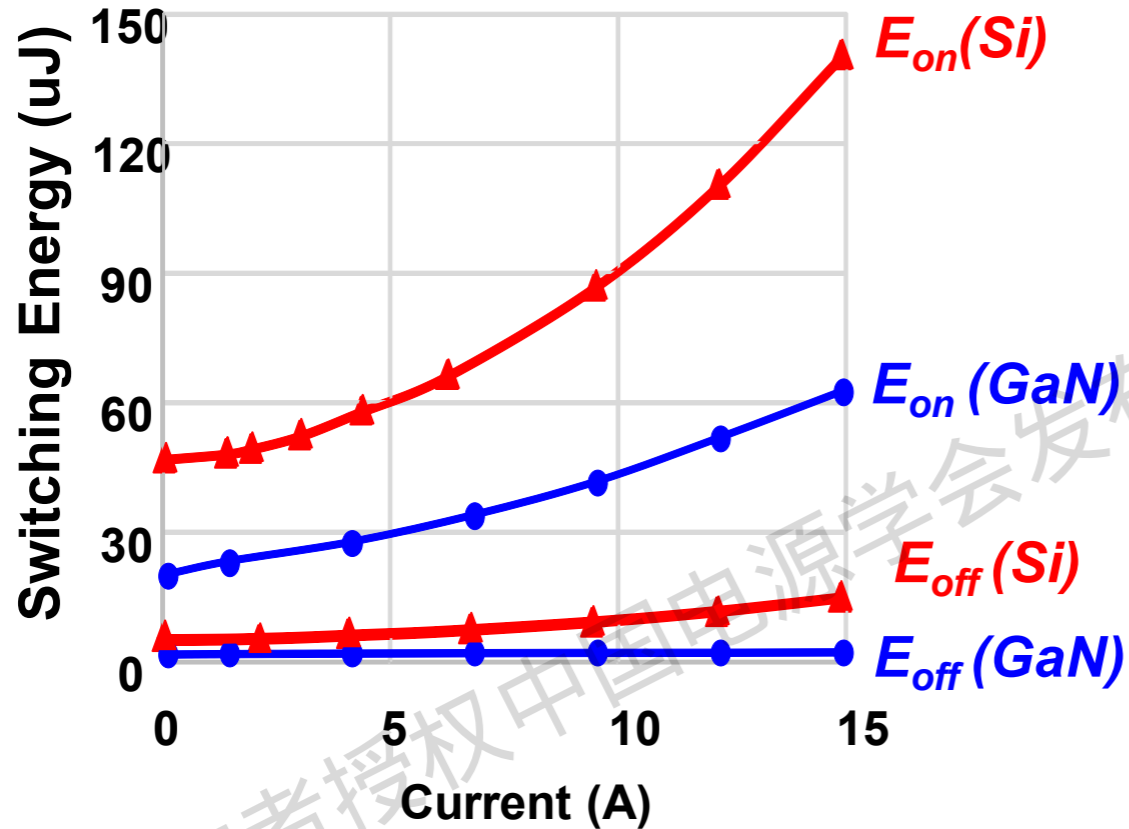


# Labor Intensive Manufacturing



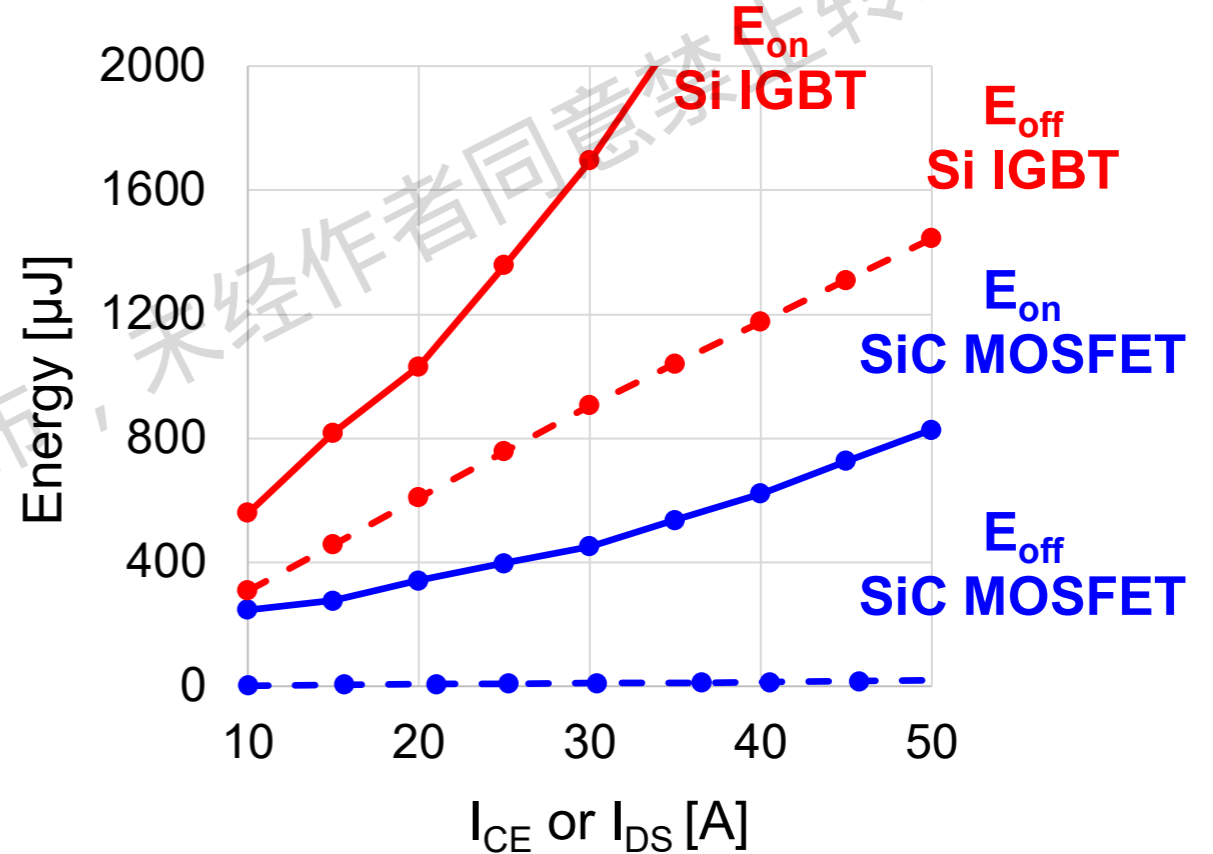
# Wide-Band-Gap vs Silicon MOSFET

## GaN. vs Si MOSFET



**GaN: 3X better**

## SiC vs IGBT

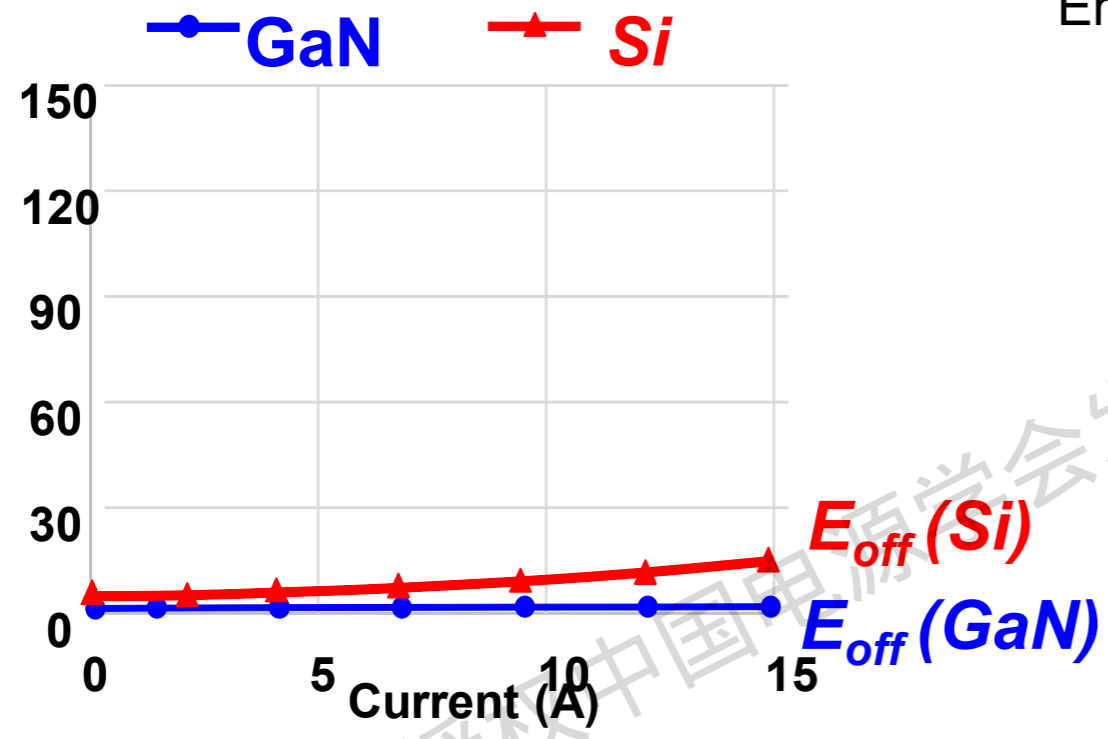


**SiC: 3X better**



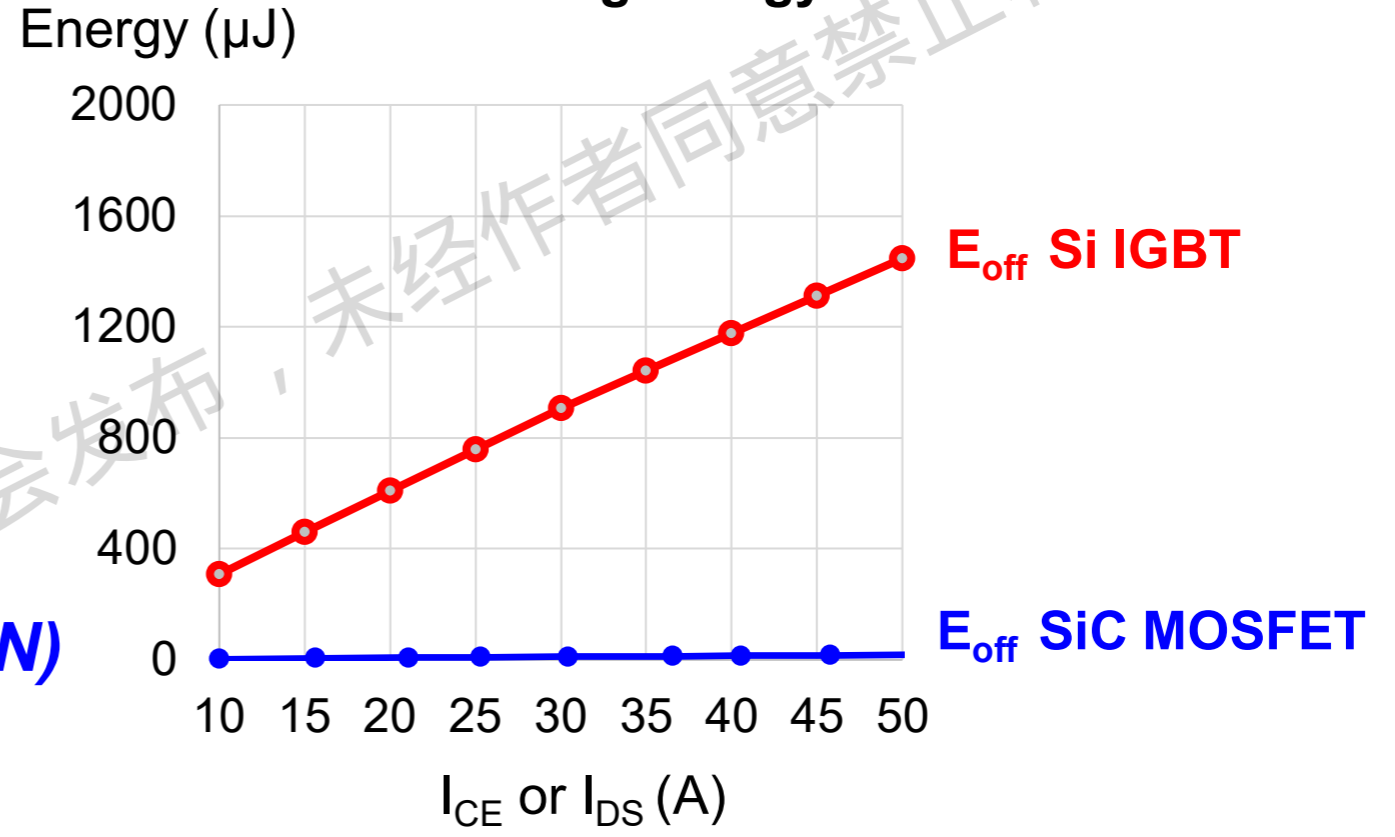
# GaN vs Silicon MOSFET

**With ZVS**



**GaN: 10 - 20X better than silicon**

**Switching Energy**

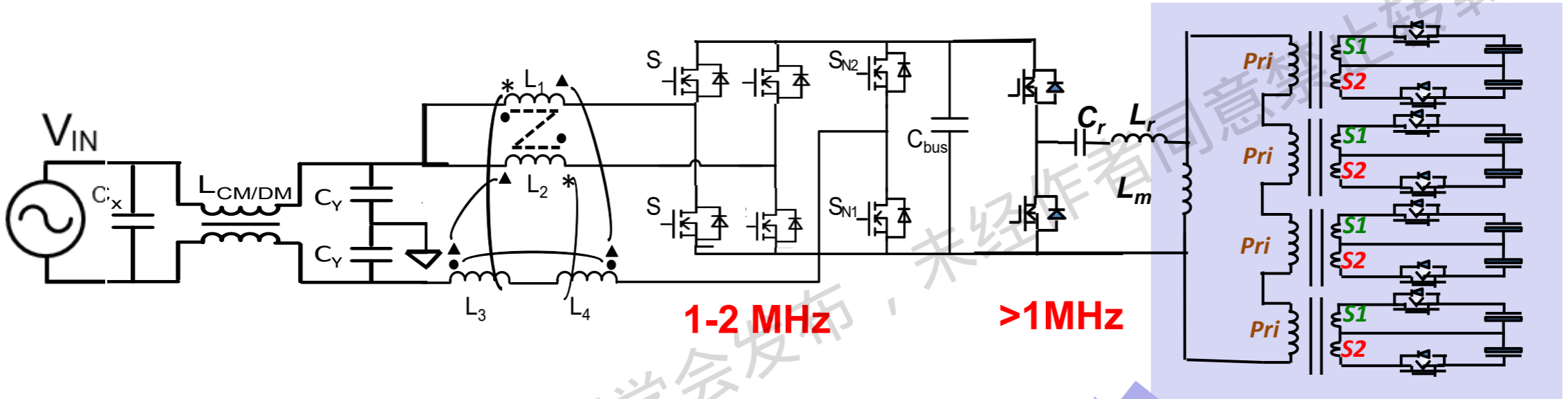


**SiC: 10 - 20X better than IGBT**

# GaN Based Integrated Power Supplies

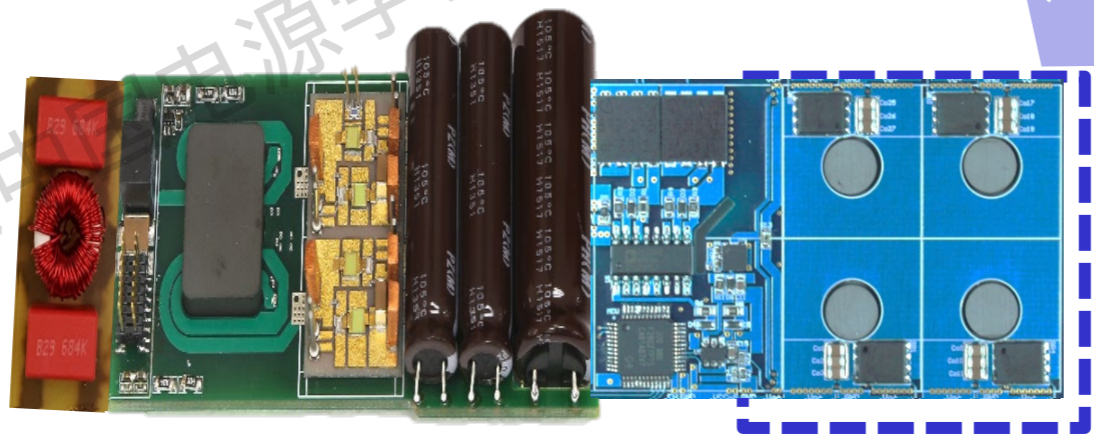
**1KW @ 1MHz**

**4:1:1**



**1-2 MHz**

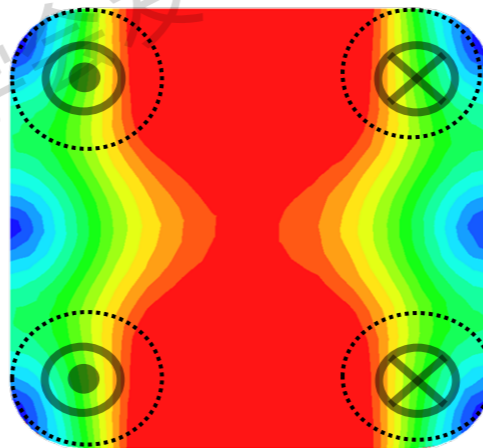
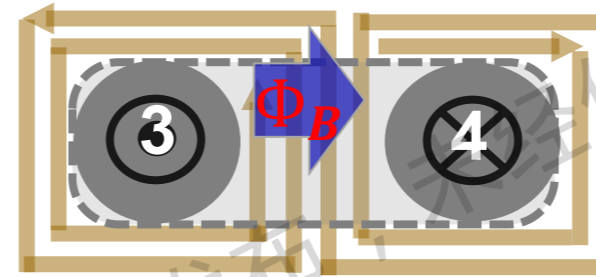
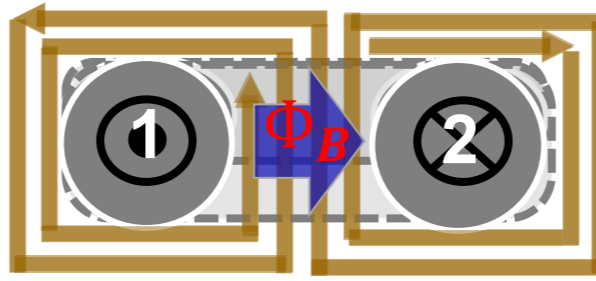
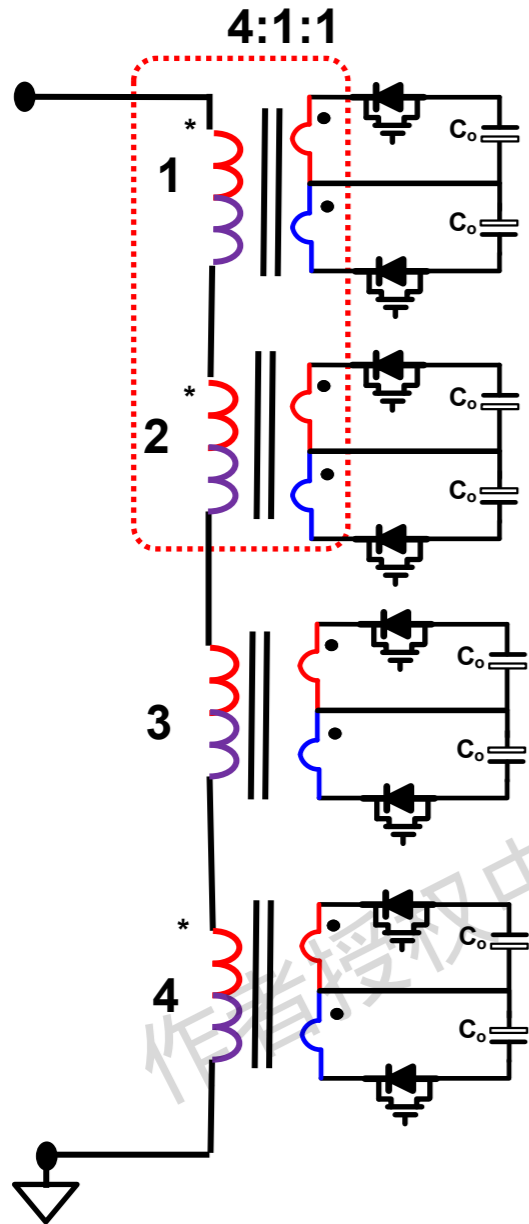
**>1MHz**



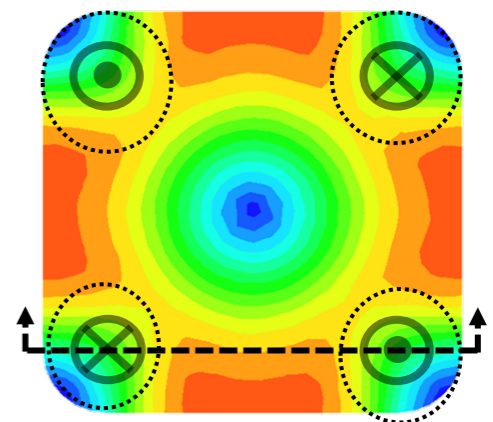
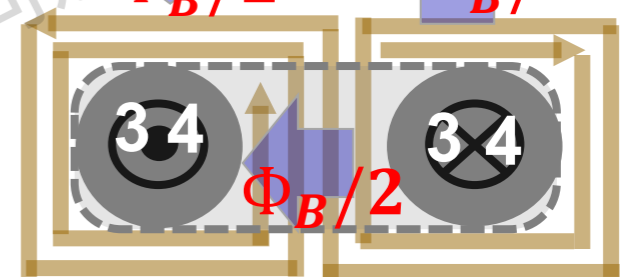
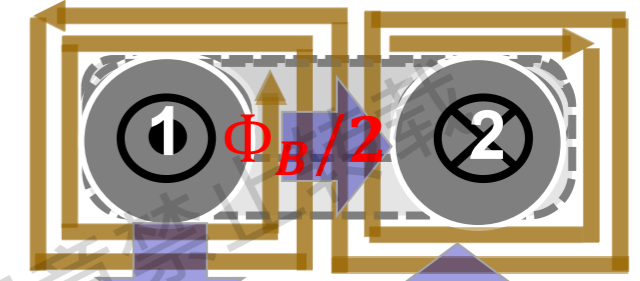
**Heterogeneous Integration via PCB**

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# Integration of 4 Transformers in 4 Layer PCB



60% volume reduction

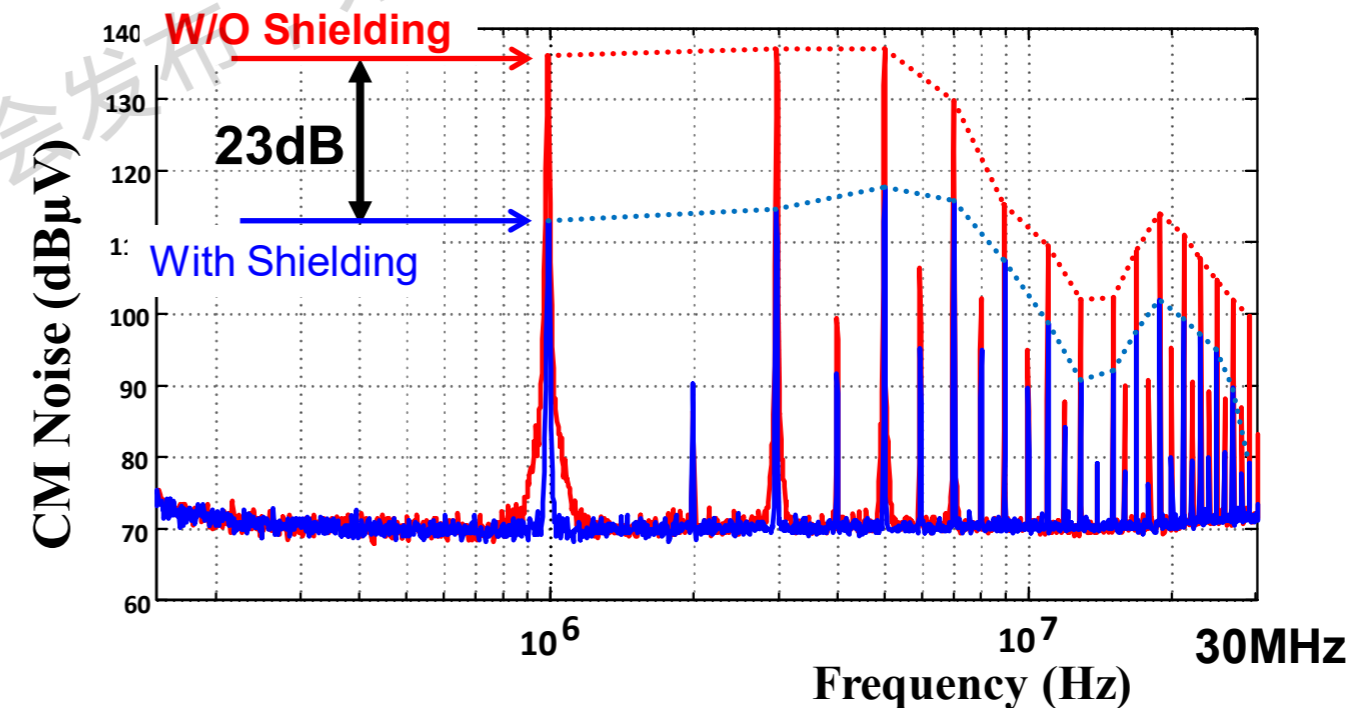
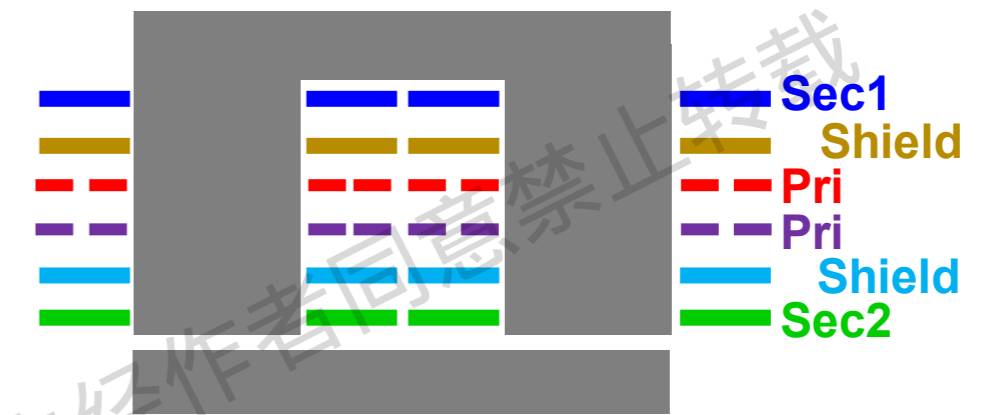
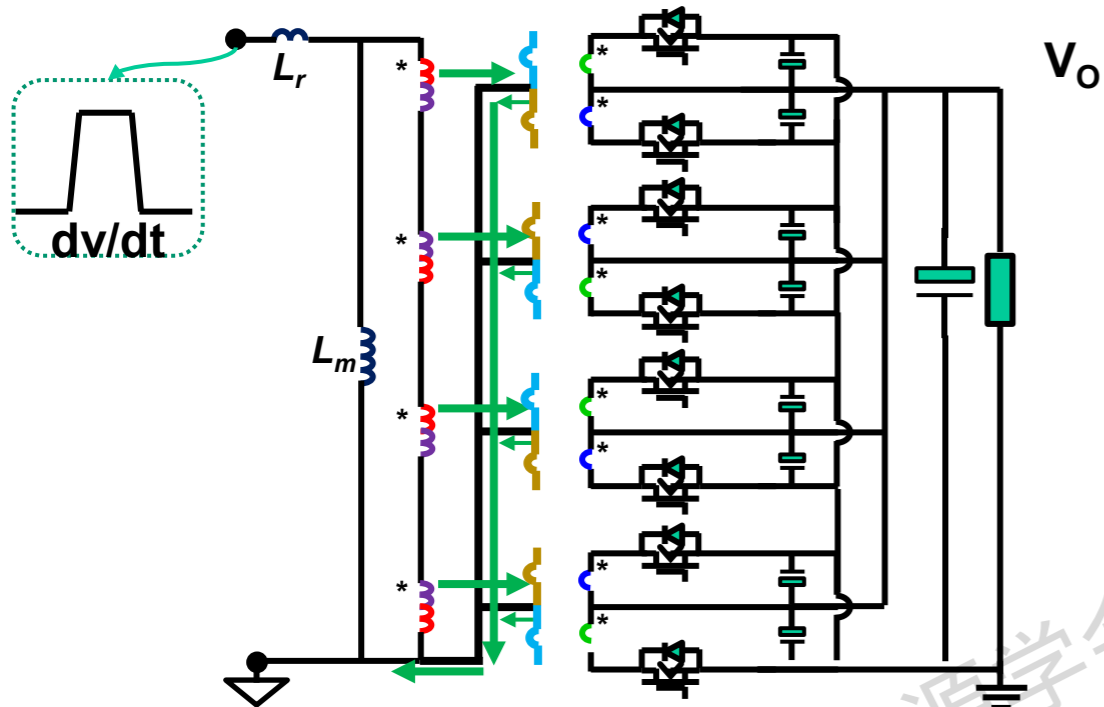


75% volume reduction

25% core loss reduction



# CM Noise Reduction by Shielding

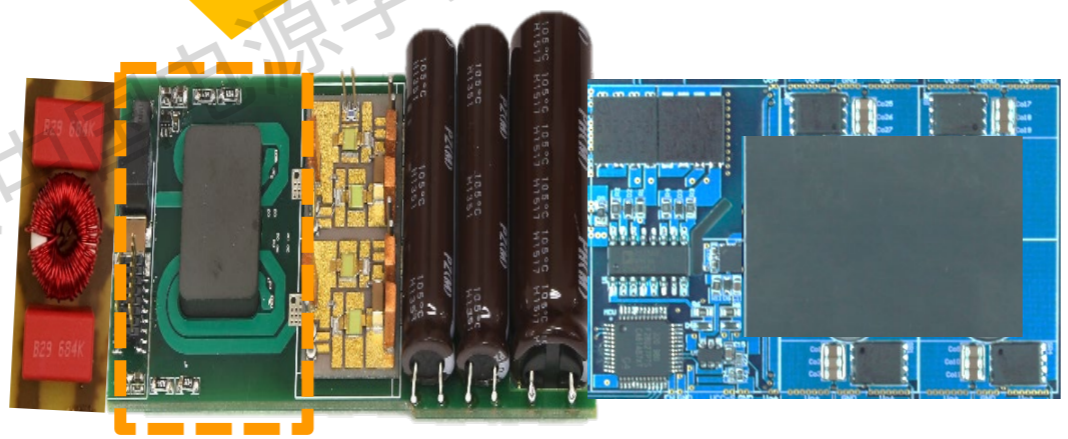
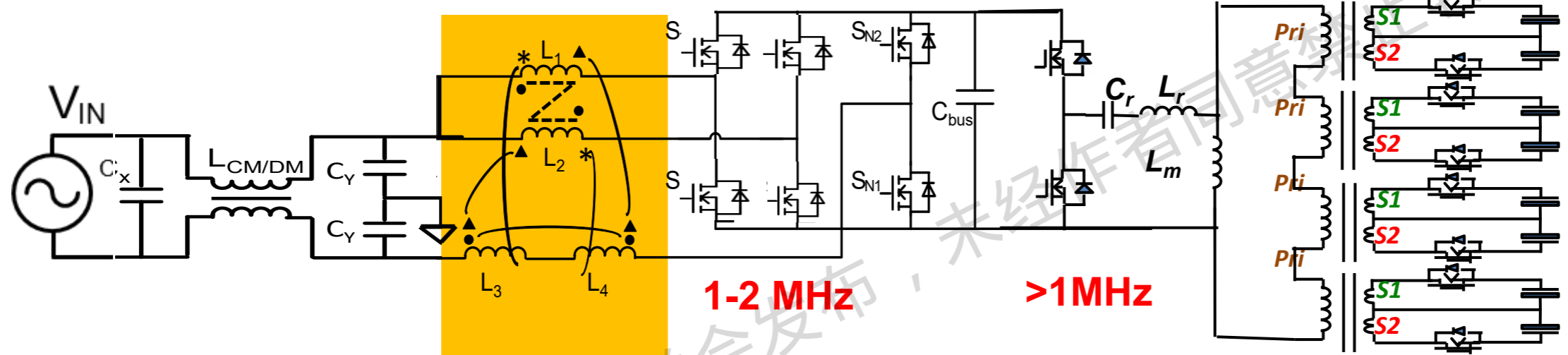


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# GaN Based Integrated Power Supplies

**1KW @ 1MHz**

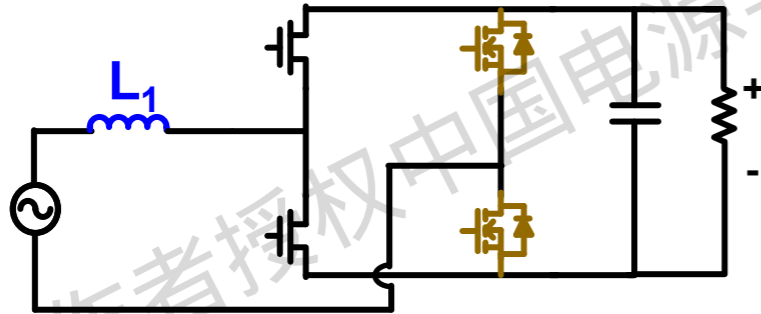
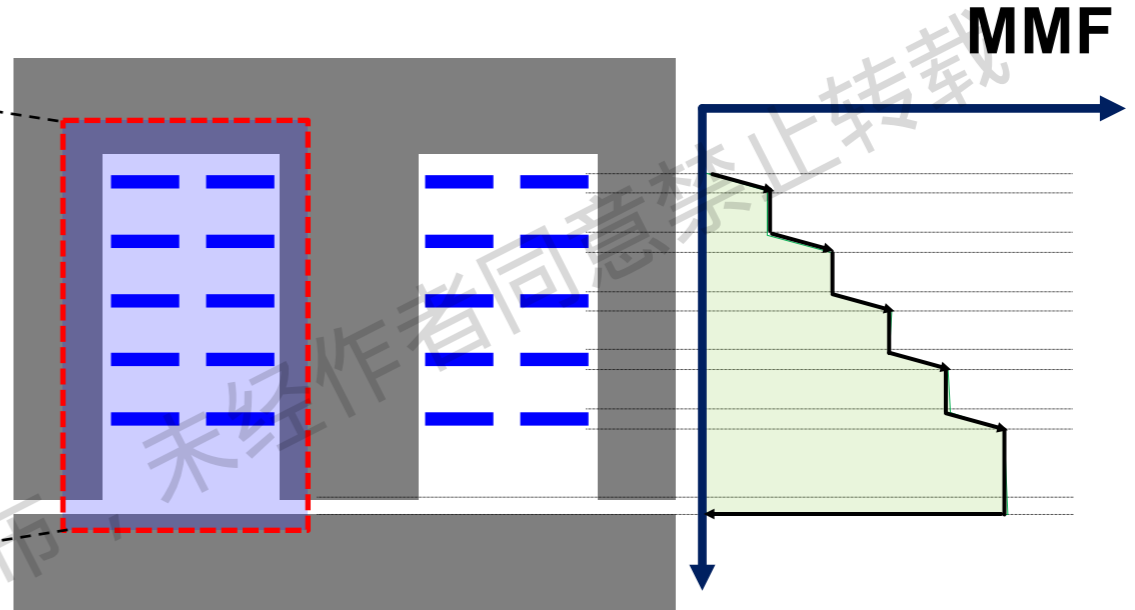
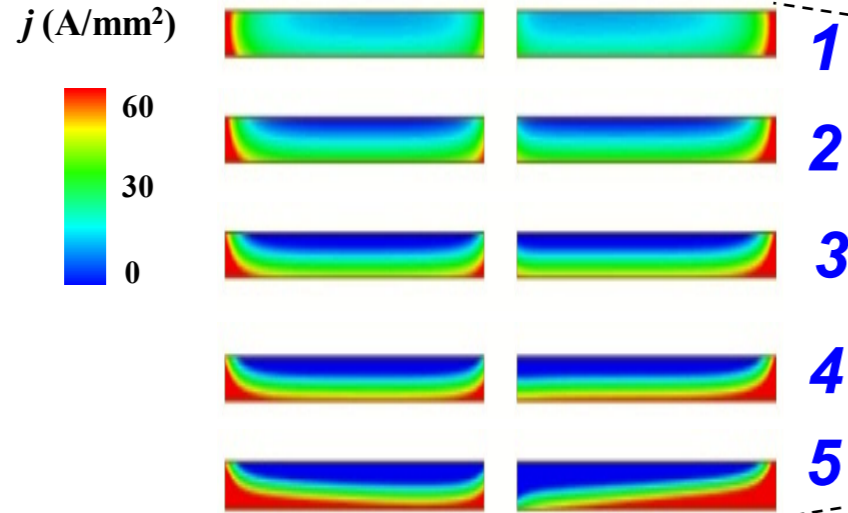
**4:1:1**



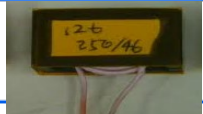
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# Issue with PCB Based Inductor

Current density by FEA



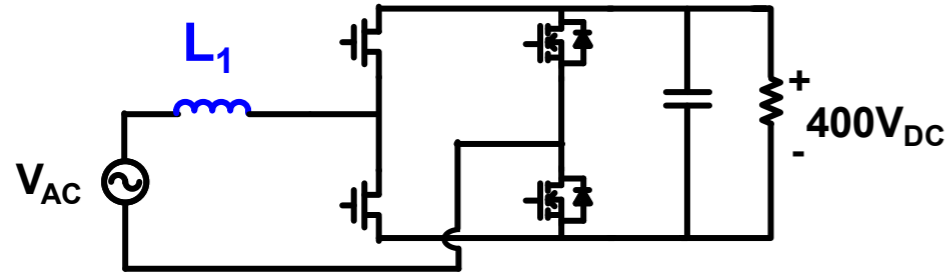
$F_s > 1\text{MHz}$

	Winding Loss (W)	Core Loss (W)	Total Loss (W)
PCB w/o interleaving	4.5	2.3	6.8
	2.3	2.3	4.6

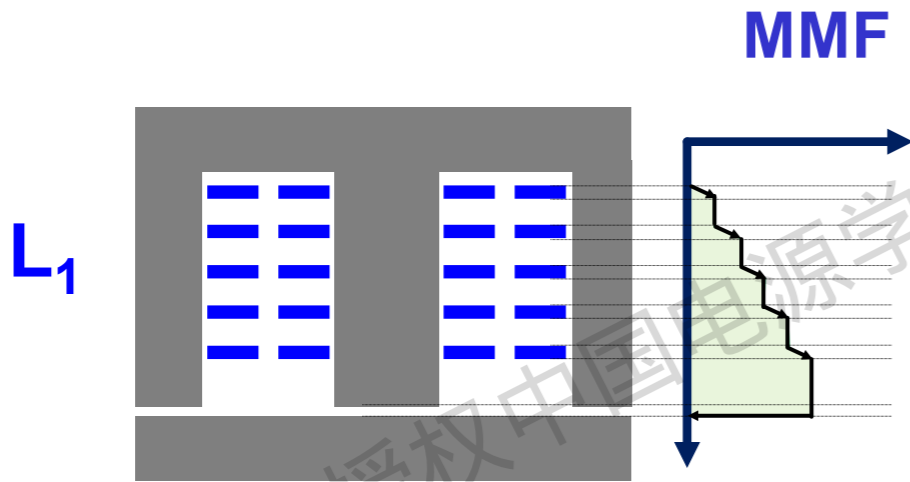
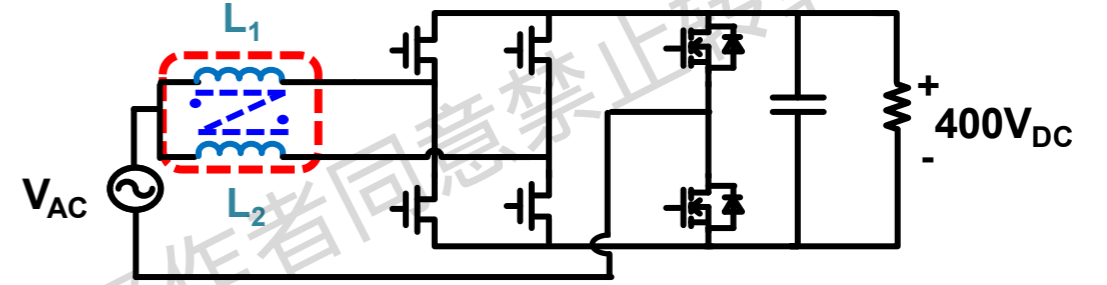
Large winding loss for PCB-based inductor

# Solution: Reducing Winding Loss by Interleaving

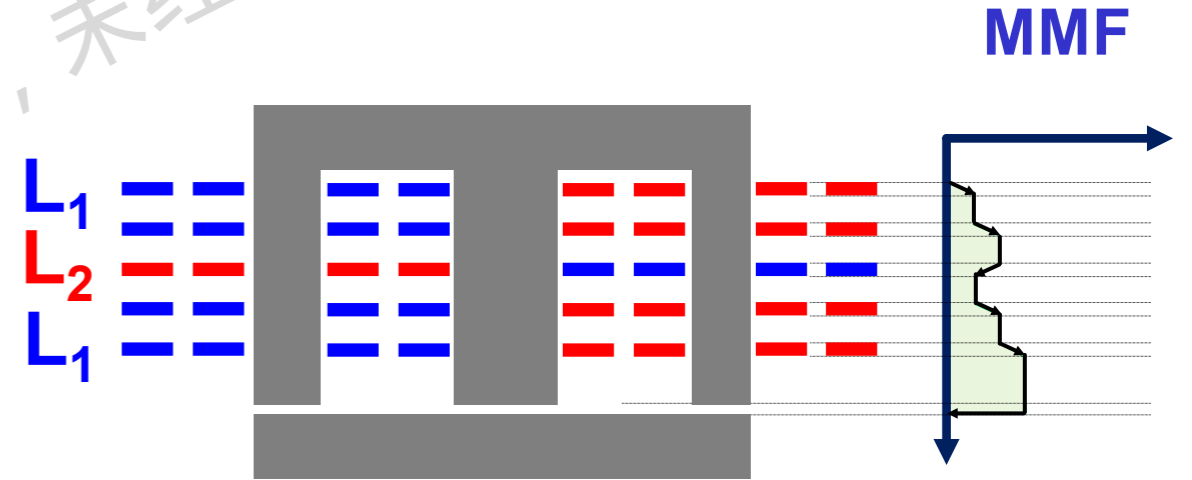
1kW, 1-2MHz



Inversely coupled inductors



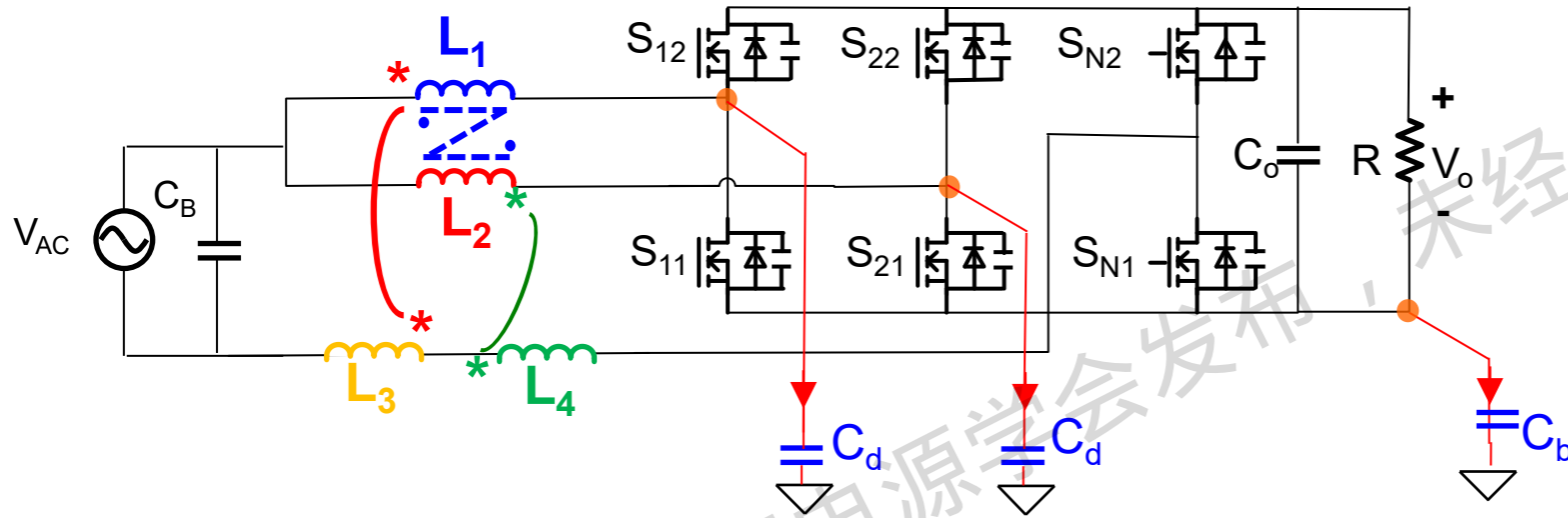
Winding Loss: 4.5W



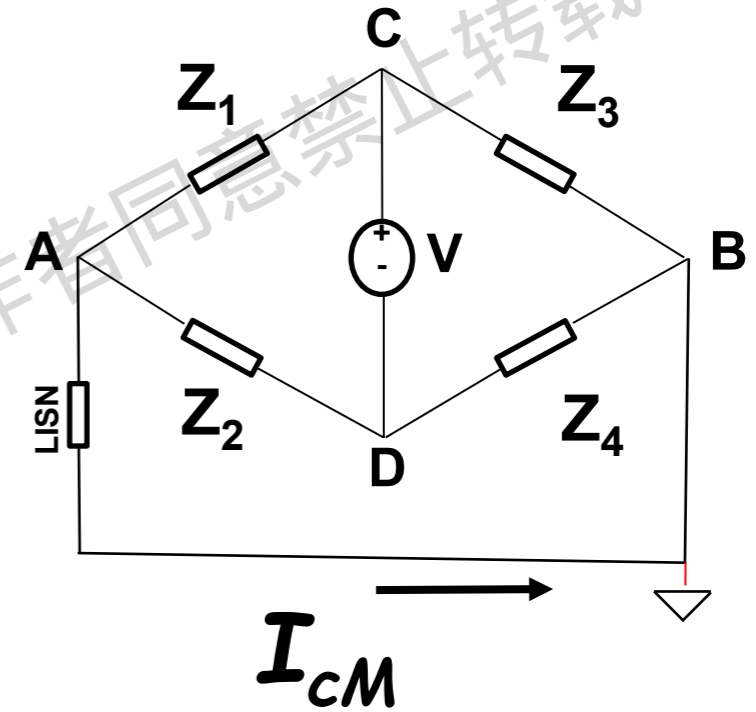
Winding Loss: 2.6W ✓

Interleaving reduces winding loss by 40%

# CM Noises Reduction Using Balance Principle



## Wheatstone Bridge

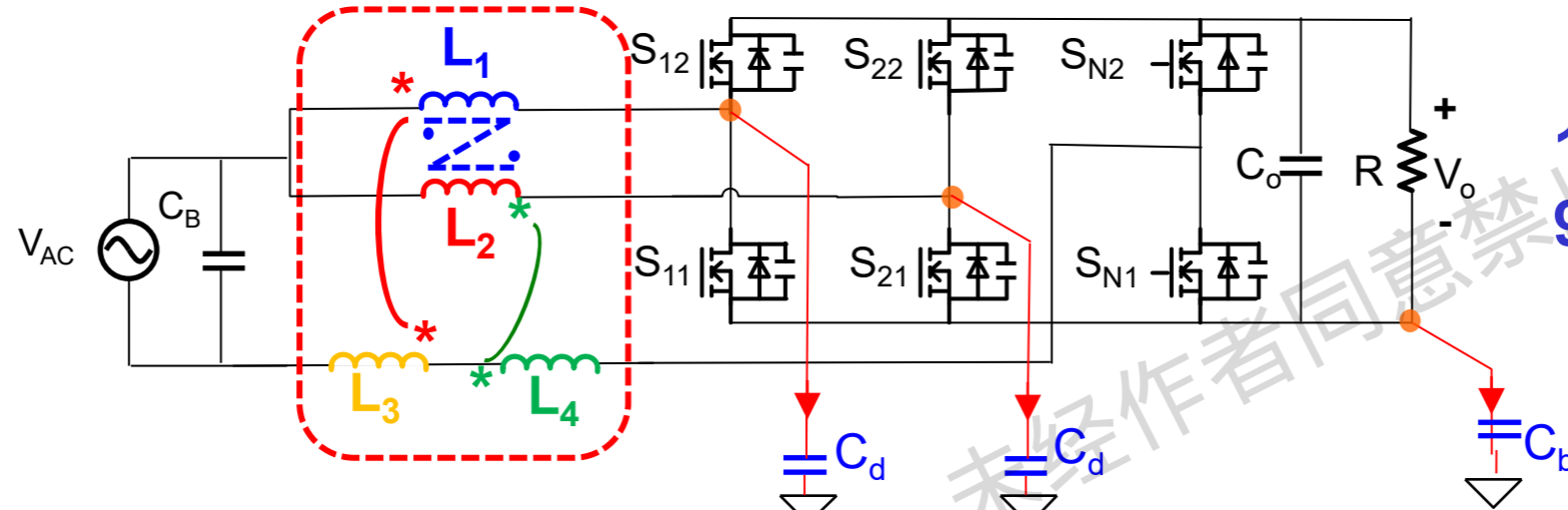


$$\frac{Z_1}{Z_2} = \frac{Z_3}{Z_4}$$

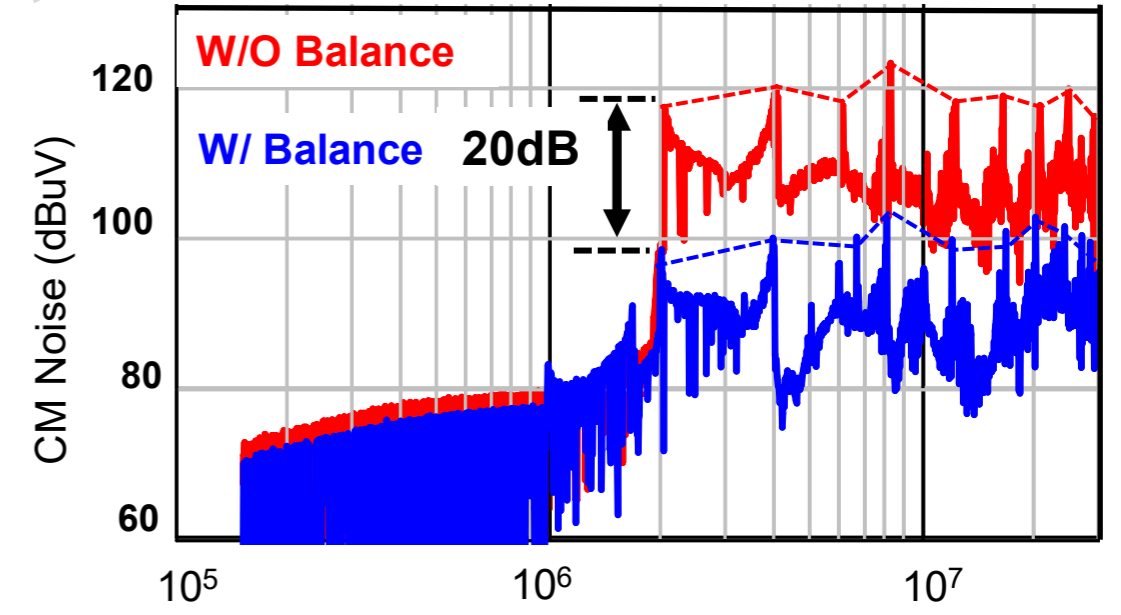
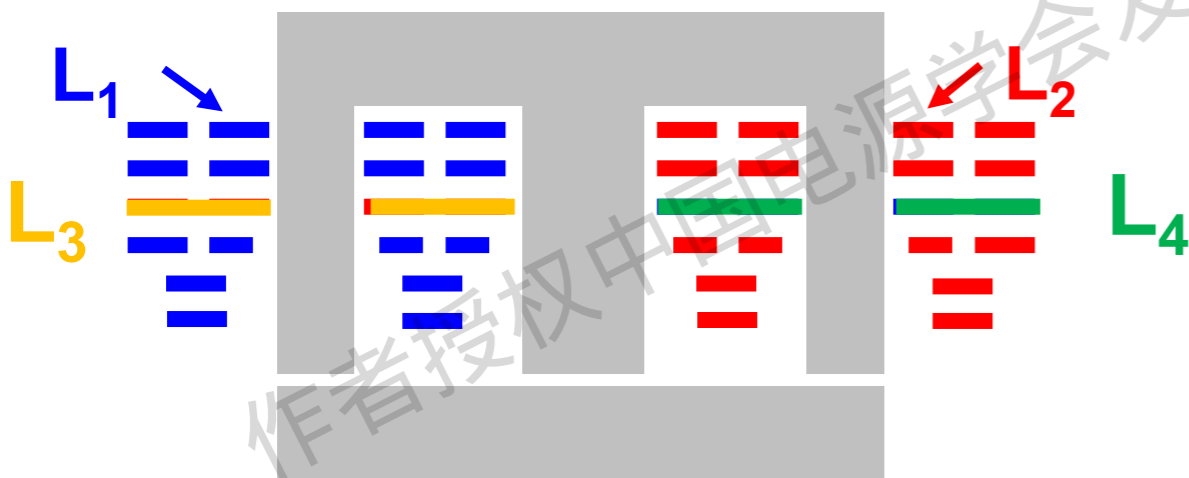
$$i_{CM} = 0$$



# Reduce CM Noises via “Balance Principle”



1KW @1-2MHz  
99% efficiency

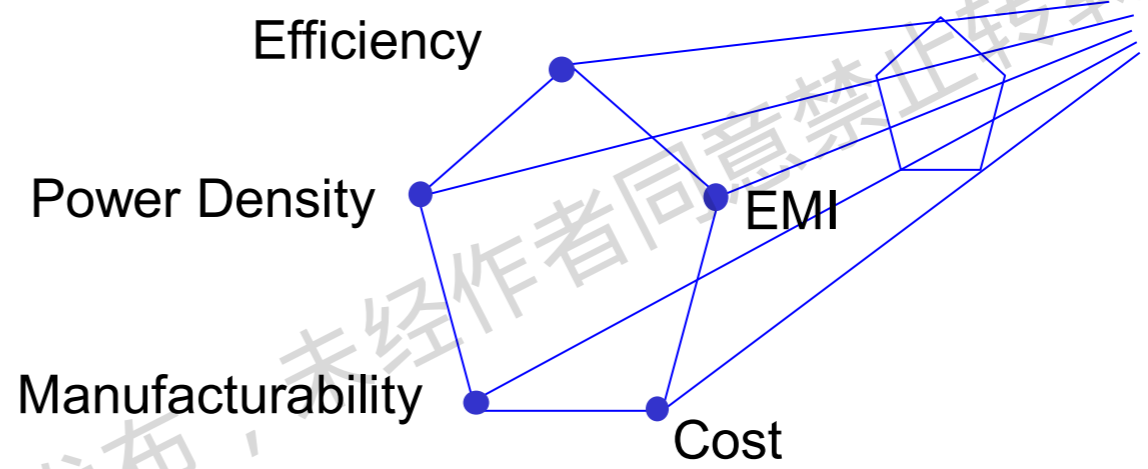


# Design Trade Off & Optimization

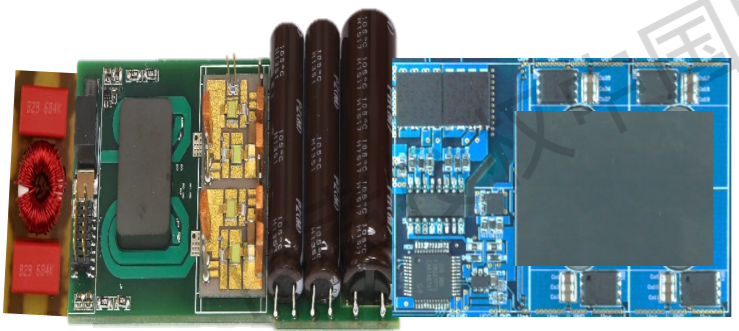
**Gen 1**      **100KHz, 1KW**



**Gen 1**      **Gen 2**



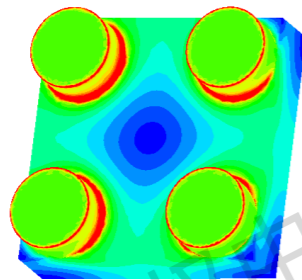
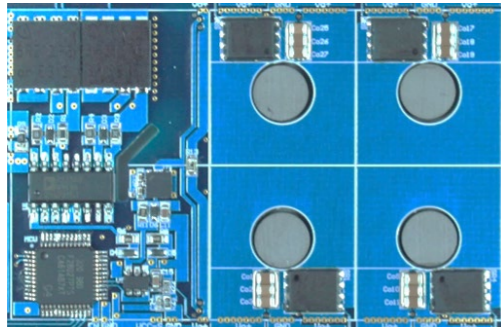
**Gen 2**      **1 MHz, 1KW**



- Eff  $\approx$  98%**
- Power density  $>$  3 – 5X**
- Improved EMI  $\approx$  20dB**
- Manufacturability**
- Low Cost**

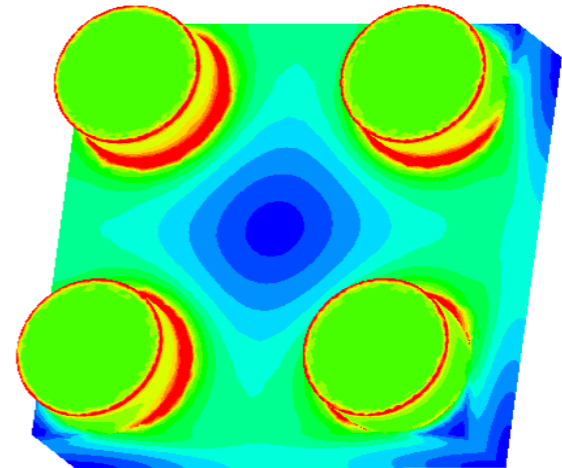
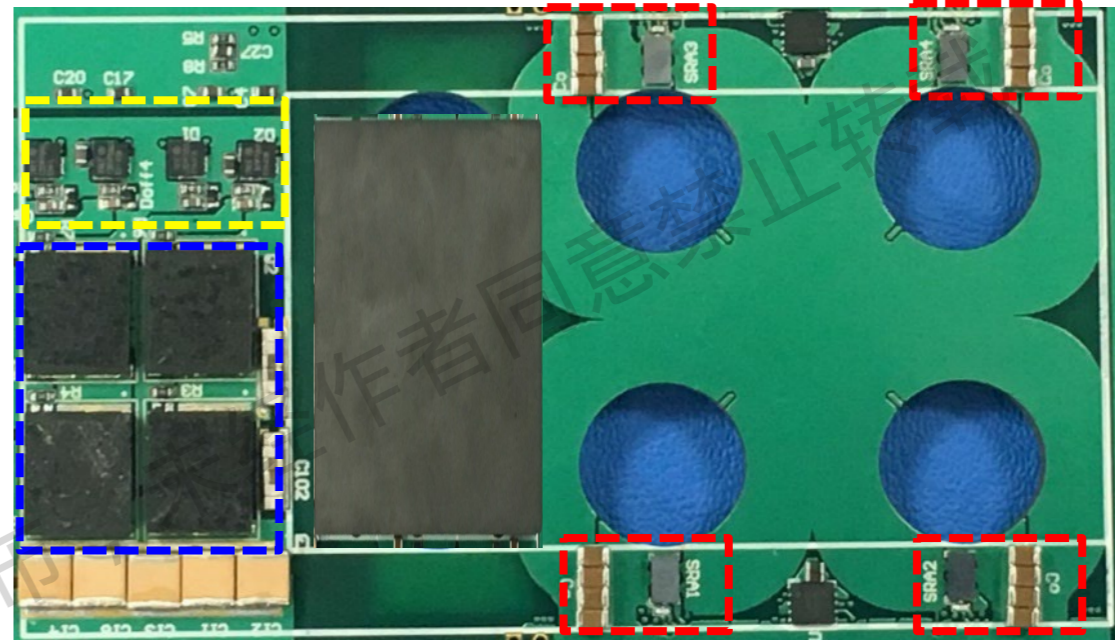
# Extended to 3KW for Gen 2 Data Center Server

1KW



1.1 W

3KW



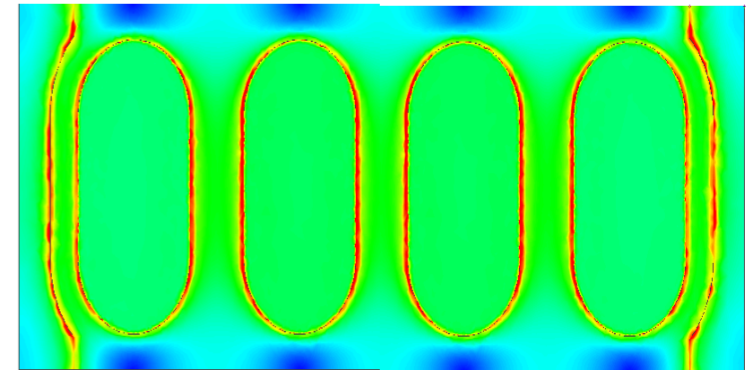
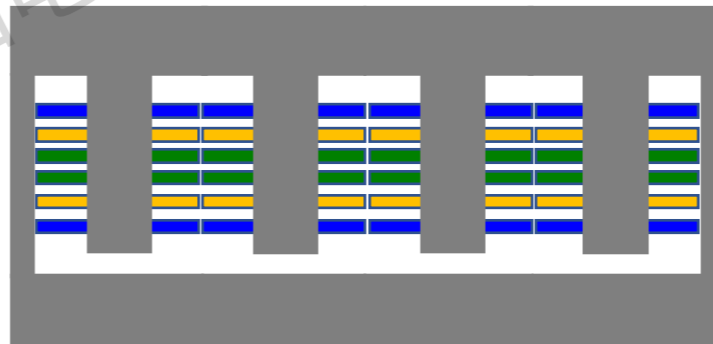
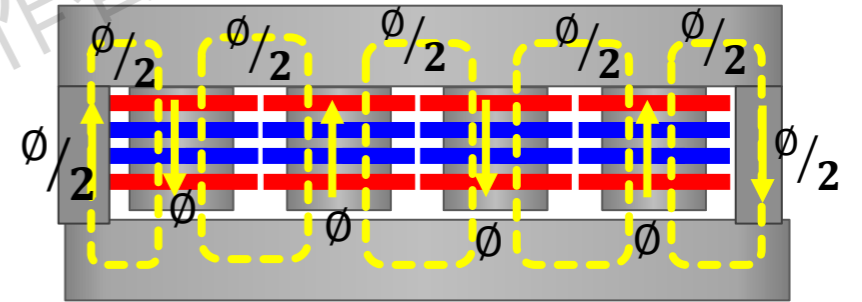
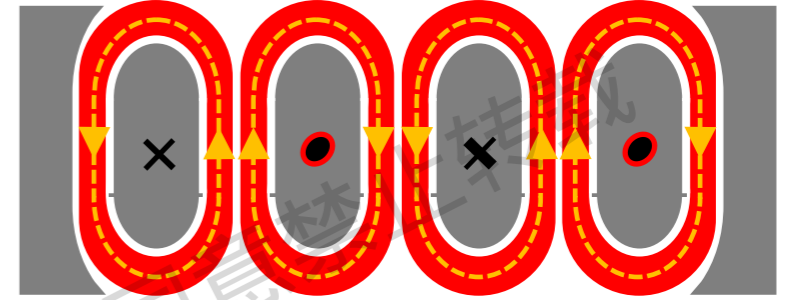
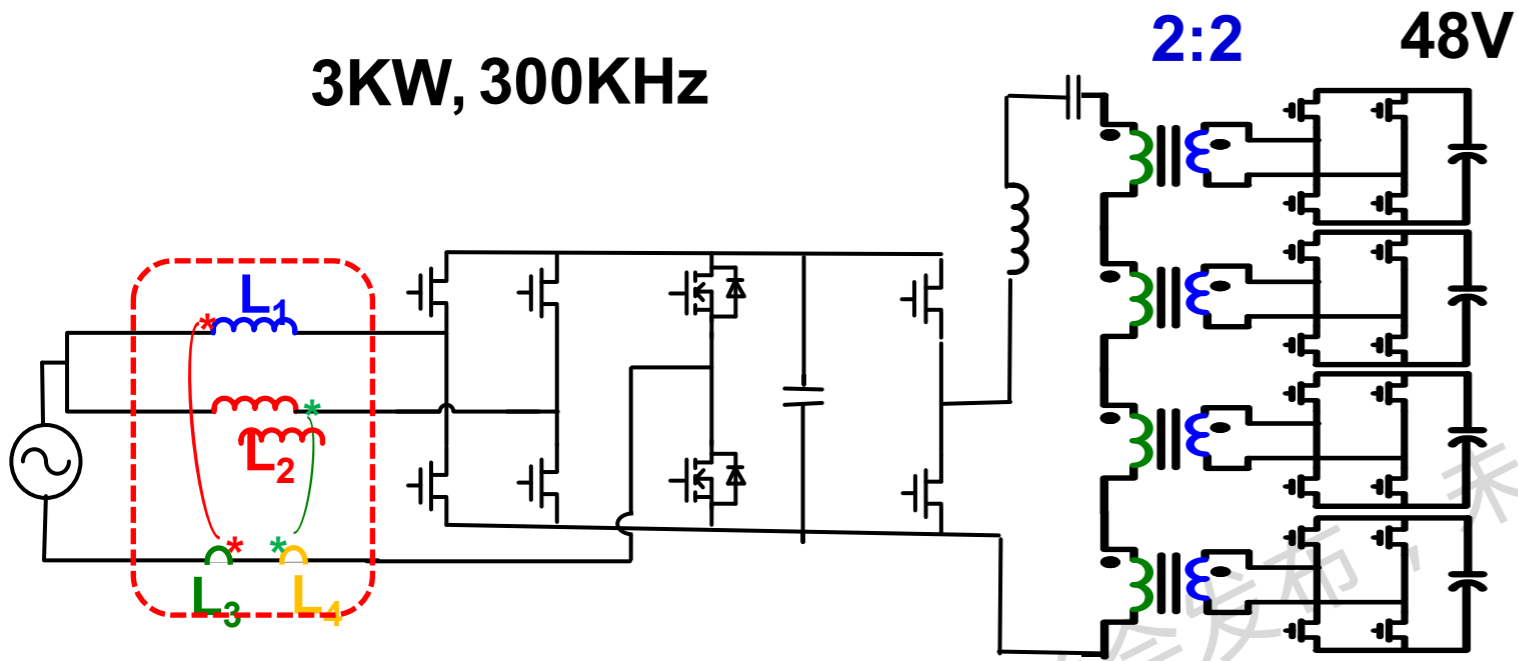
14 W

8.5 W Eddy Loss

**PCB based transformer with significant increase in core loss**

# Gen 2: Data Center Server Power Supplies

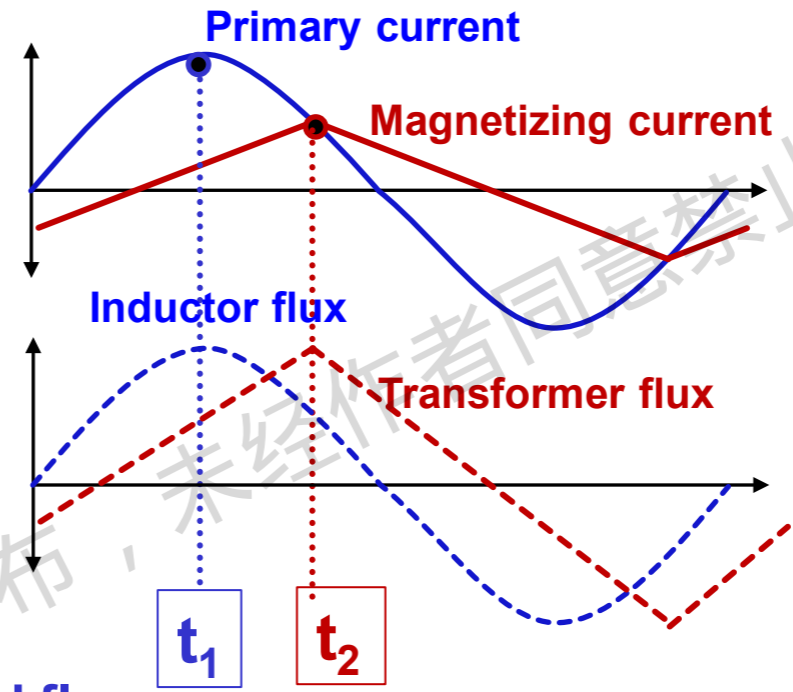
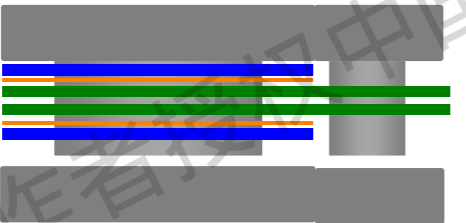
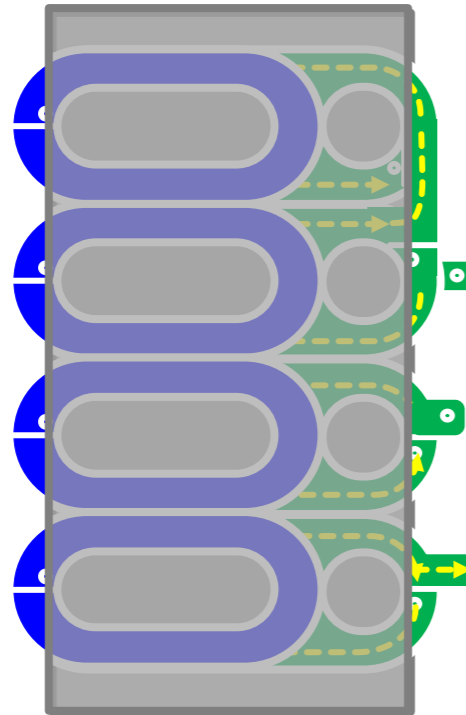
3KW, 300KHz



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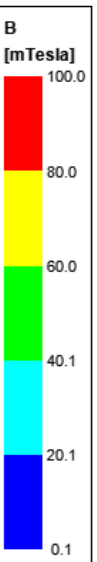
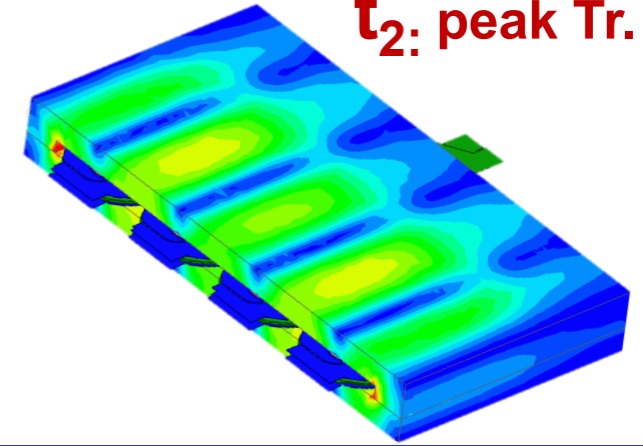
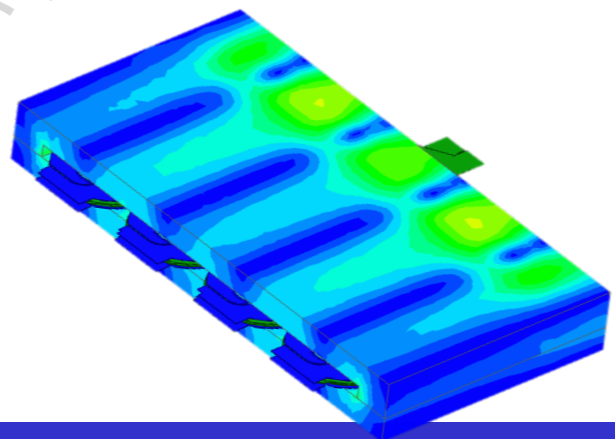
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# Inductor & Transformer Integration



$t_1$ : peak ind flux

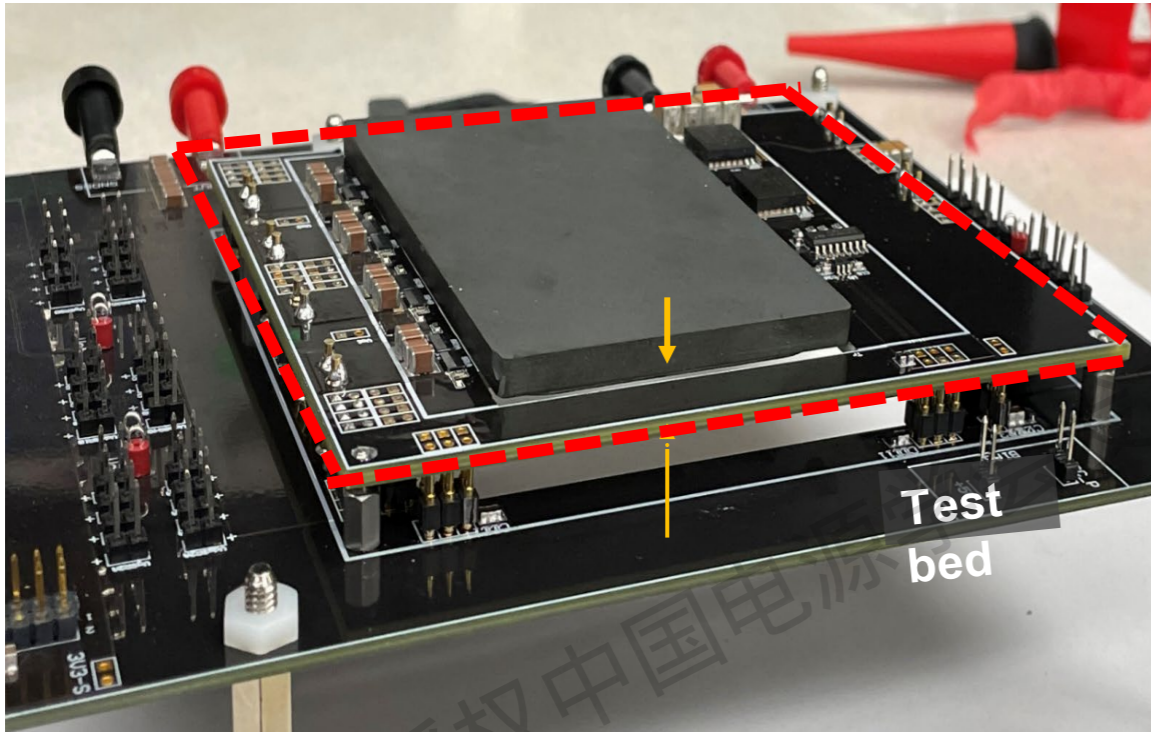
$t_2$ : peak Tr. flux



Reduction in flux density in plates (~20% reduction in core loss)

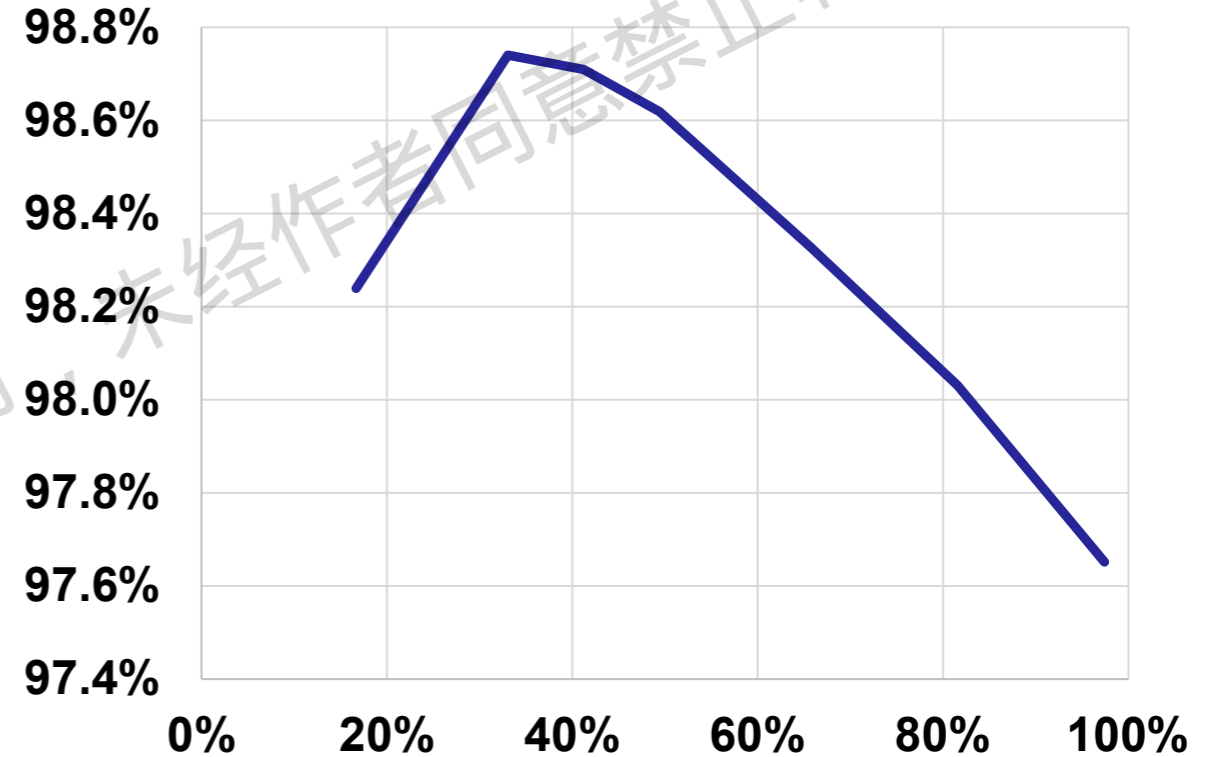
# Hardware Prototype

400V- 48V 300kHz LLC



Profile: 11mm

Power Density: 600W/in<sup>3</sup>

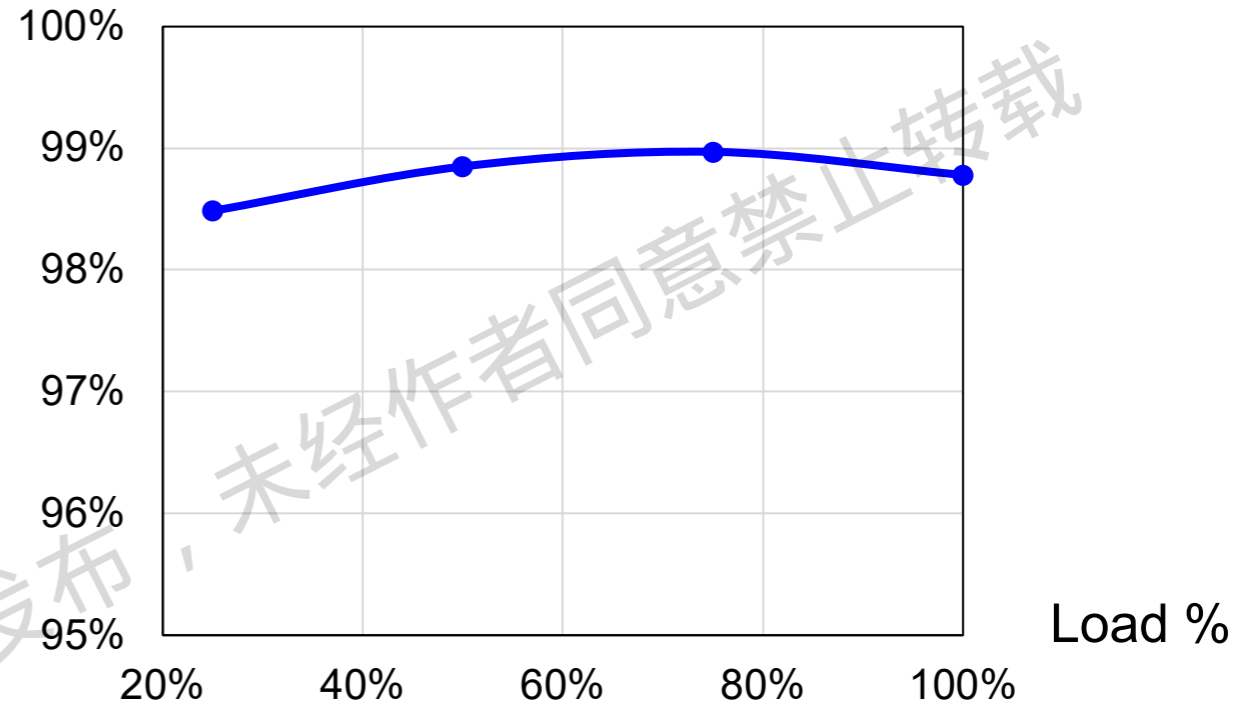
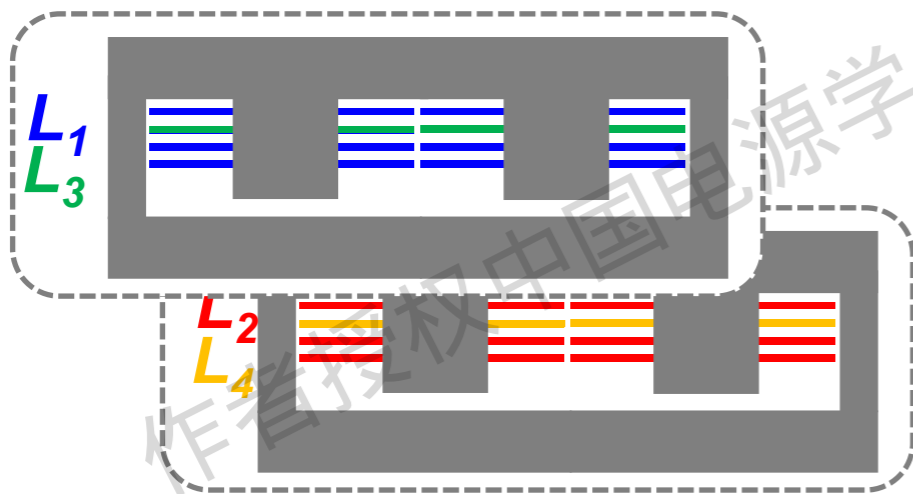
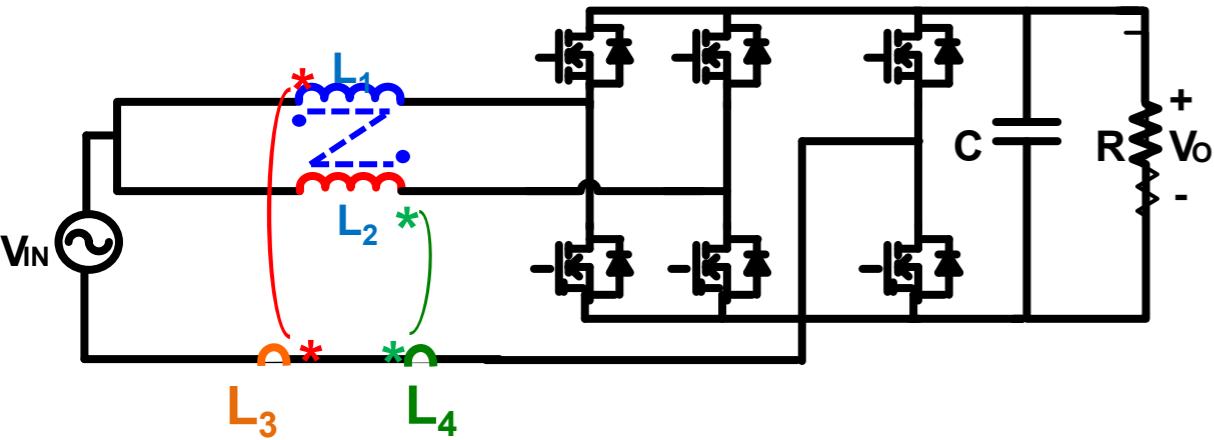


**Low profile transformer at 300kHz with the help of Integrated Magnetics**

Final design with Transformer FP = 3400mm<sup>2</sup> Inductor FP = 1400mm<sup>2</sup> (after integration)

# Magnetic Integration for 3KW PFC<sup>[7]</sup>

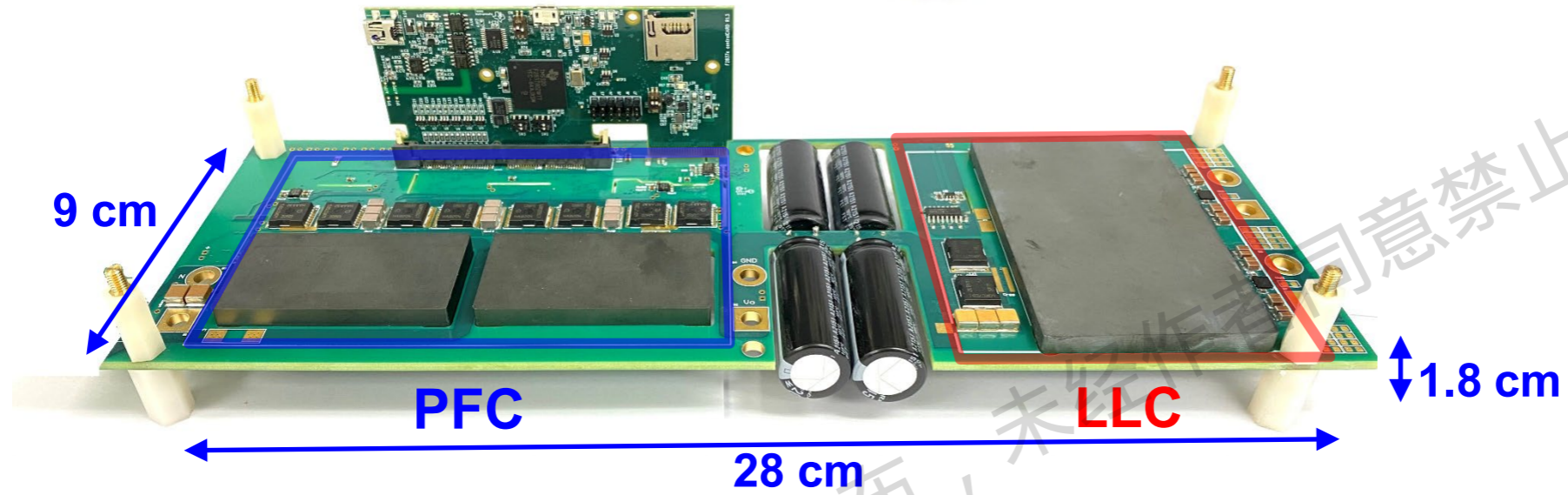
3KW @ 300KHz



	Wind Loss	Core Loss	Total Loss
PCB	6.2	6.0	12.2
Non Coupled Inductor (x2)	5.8	6.2	12.0

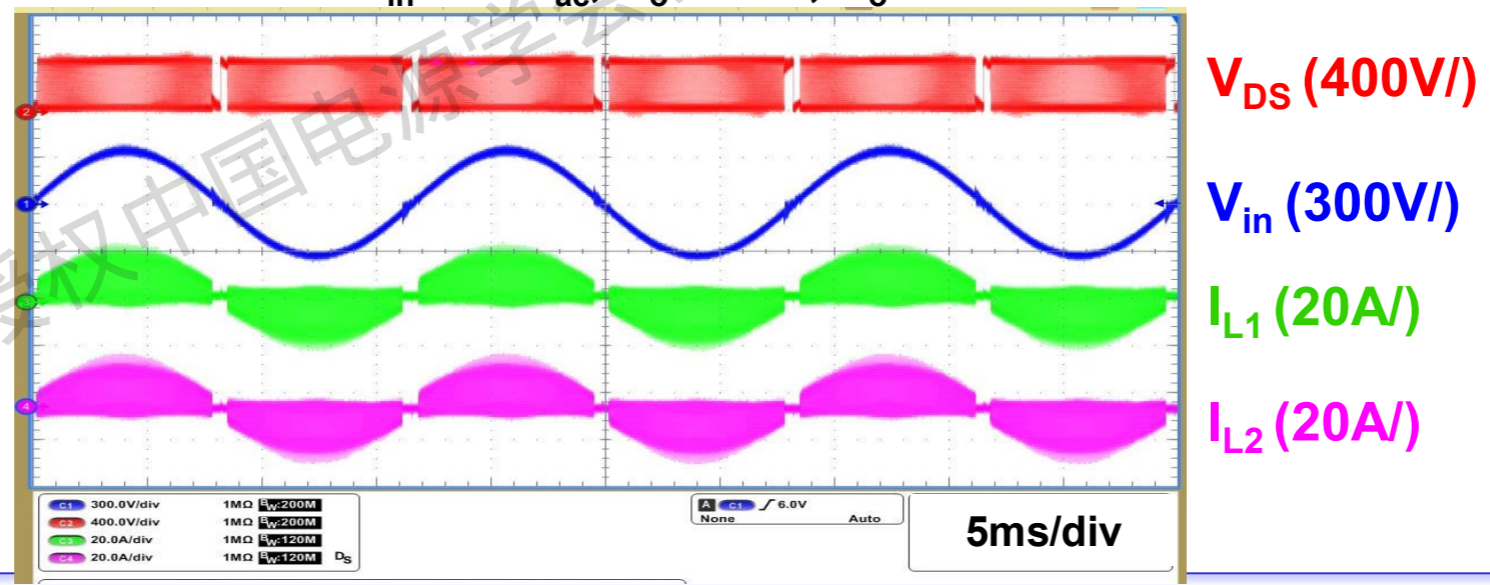


# Experiment Results



Power Density  
(w/o controller):  
**110 W/in<sup>3</sup>**

PFC:  $V_{in}=230V_{ac}$ ,  $V_o=400V$ ,  $P_o=3.0kW$

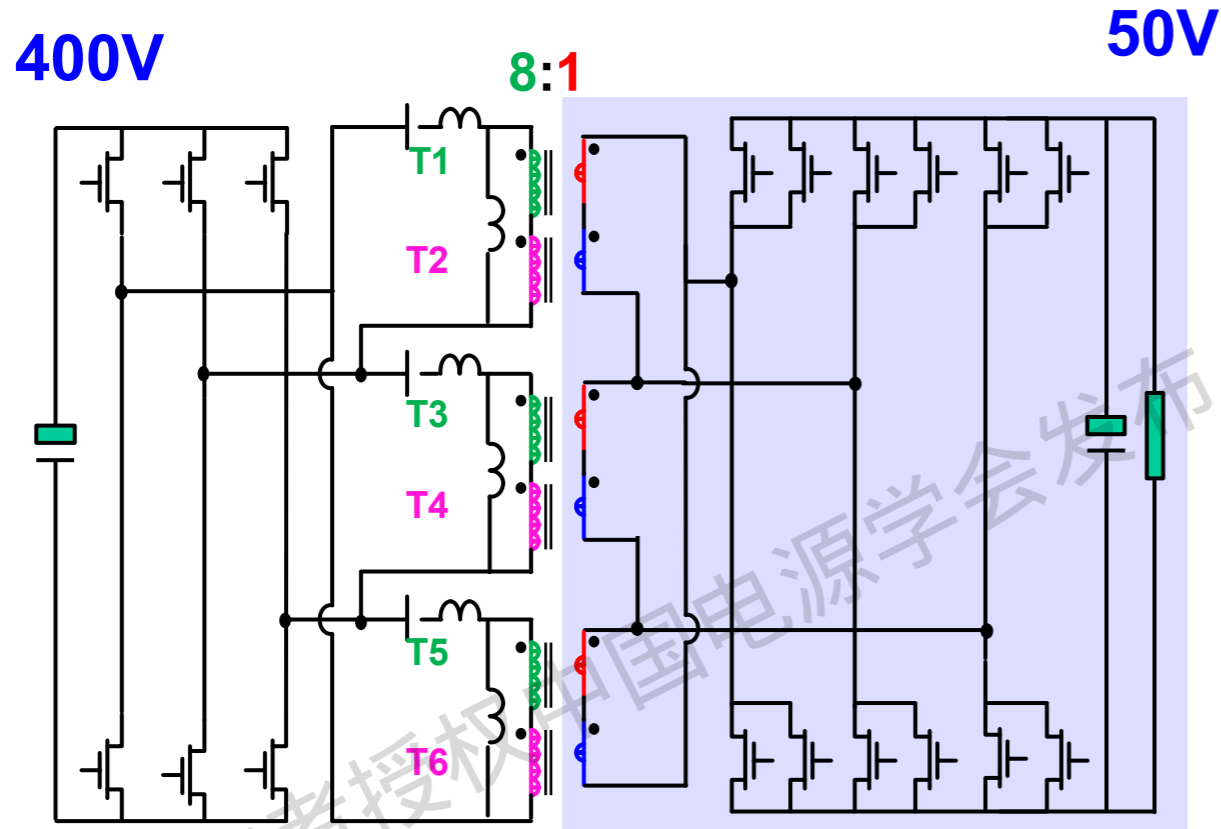


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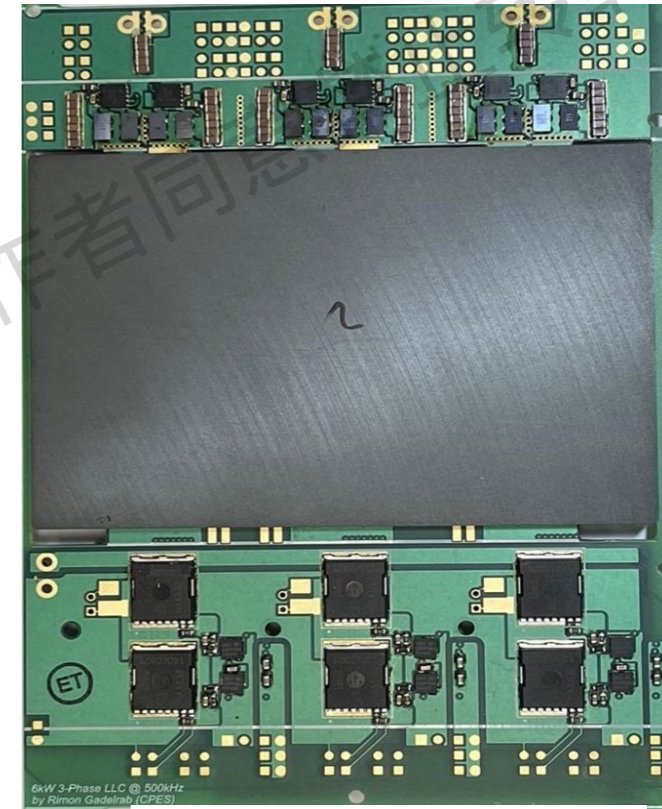


# Extended to Higher Power 6-9kW

## 3-Phase LLC



113 x 101 x 9 (mm)



6-layer PCBDC-

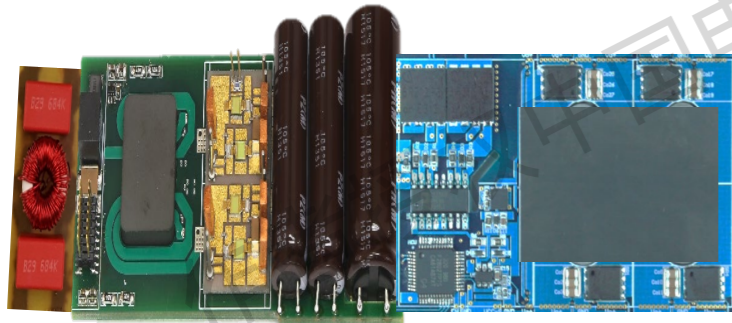
~ 99%

~ 300-400 W/in<sup>3</sup>

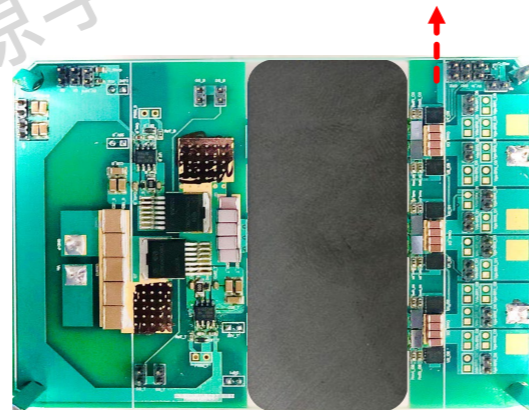
# A Paradigm Shift



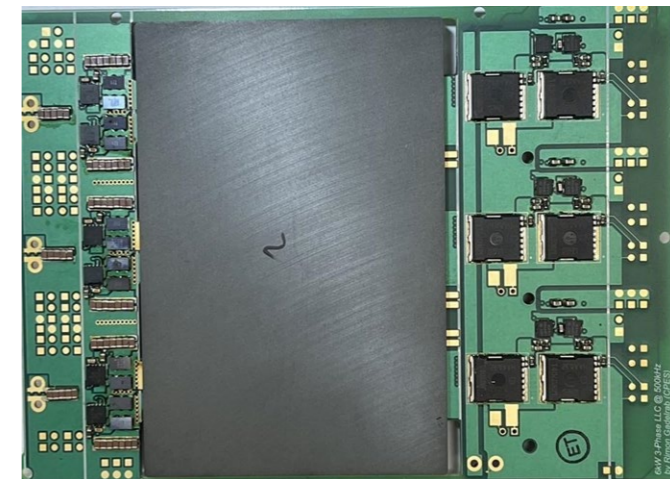
**Product Specifications**



**1KW Server Power**



**3KW Server Power**



**6-9 KW Server Power**

**Thank You**

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